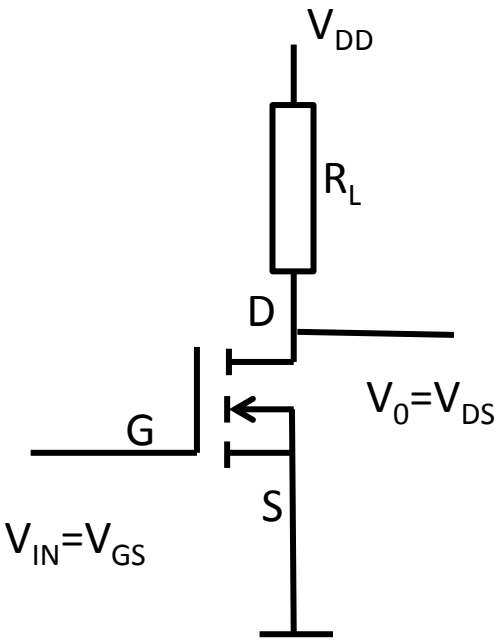
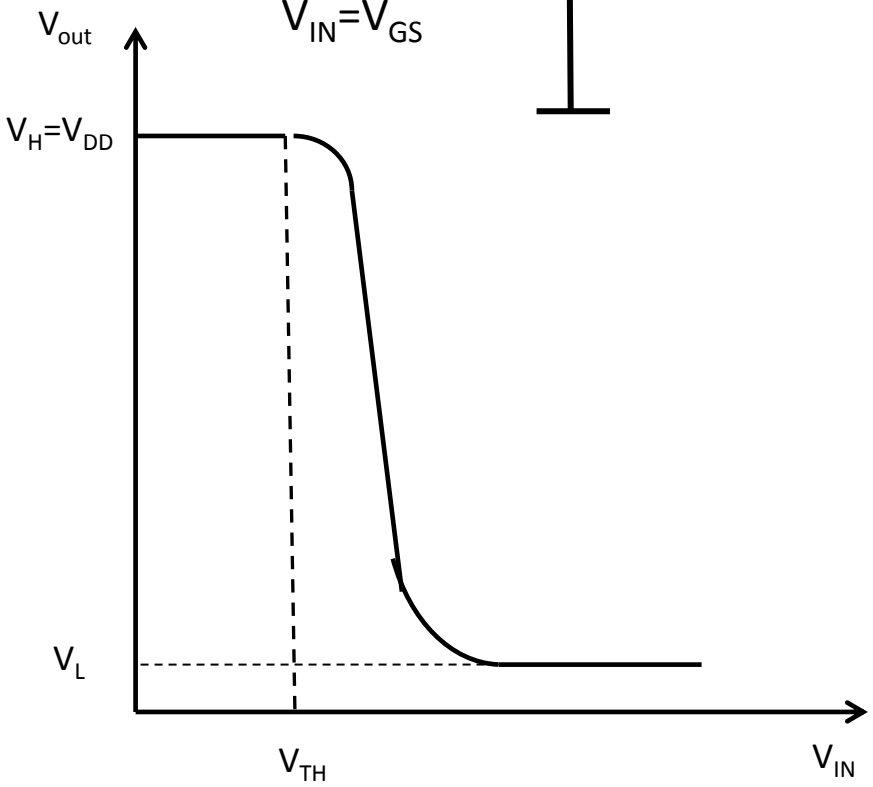
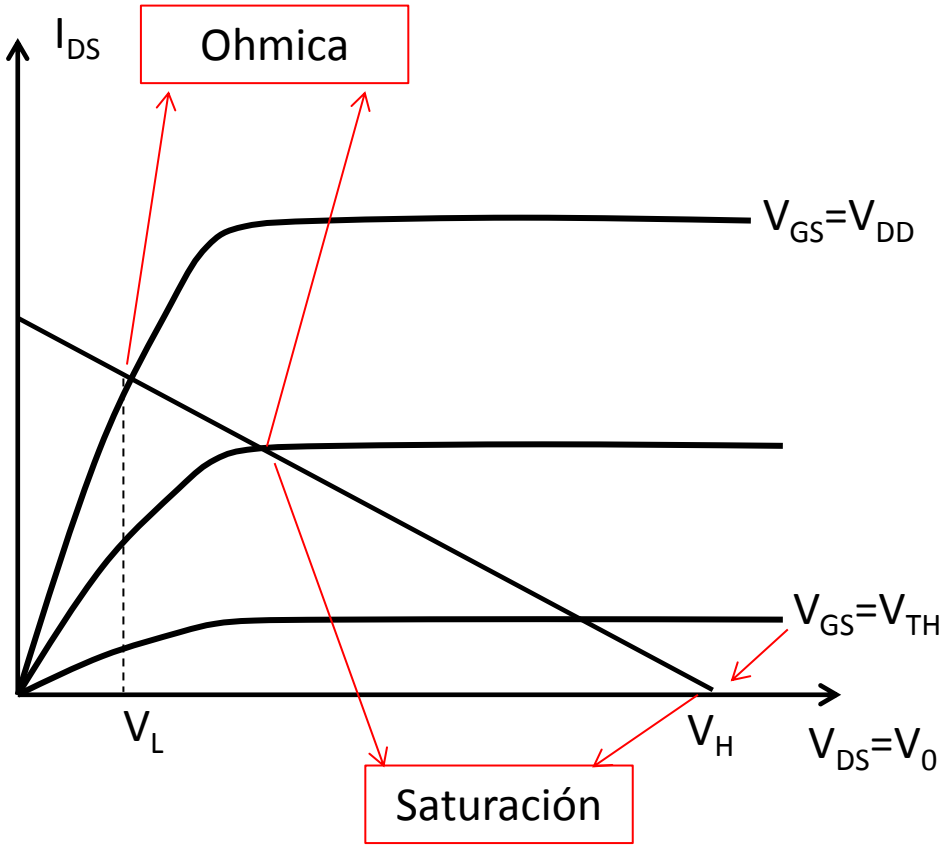
Inversor NMOS

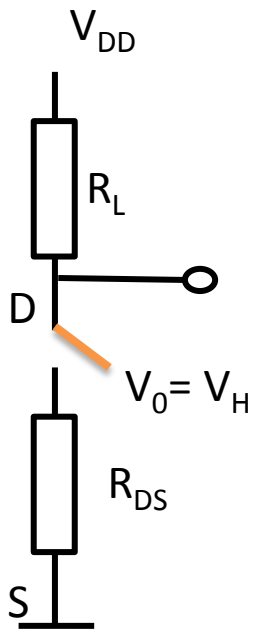




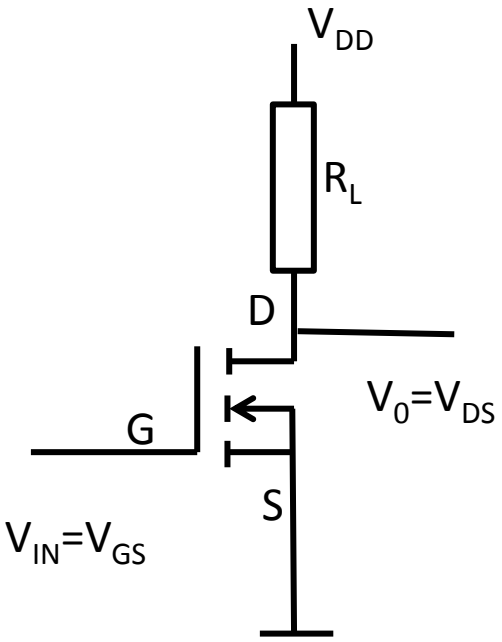


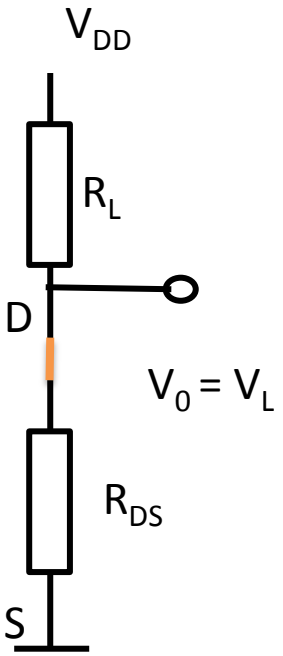
- Al variar V_{IN} desde 0 a V_{DD} el MOS pasa por:
  - Ï Zona de corte
  - ÏÏ Zona de saturación
  - ÏÏÏ Zona óhmica

Inversor NMOS



Salida en estado lógico alto

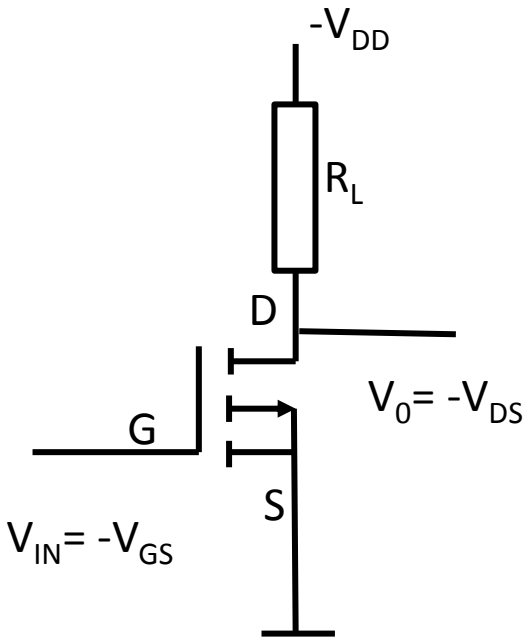


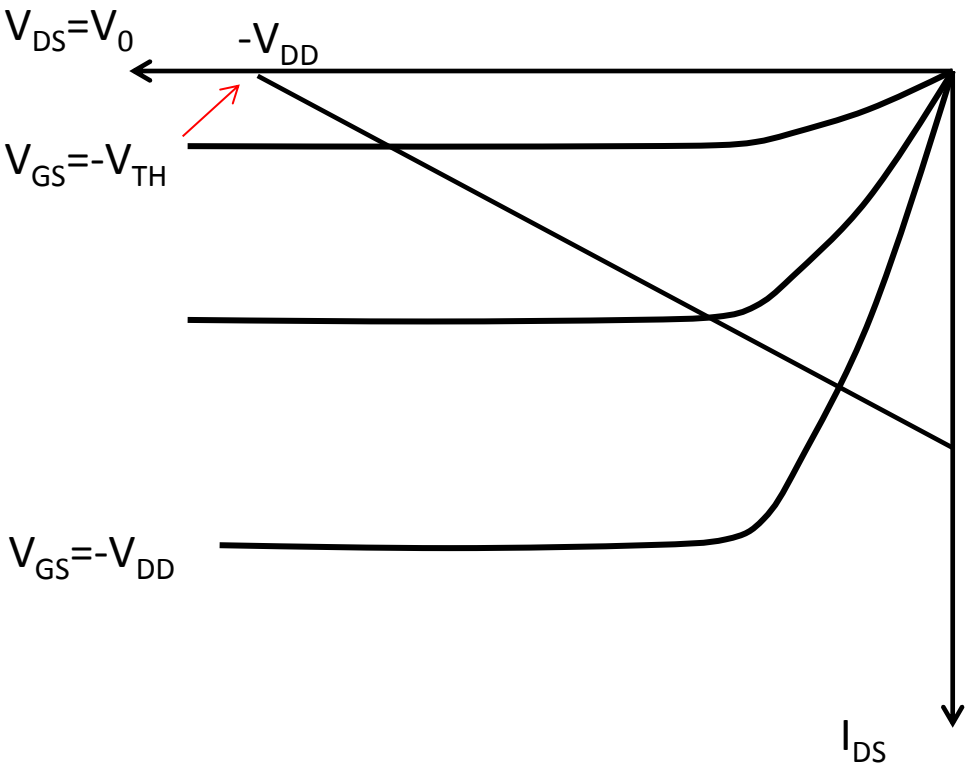


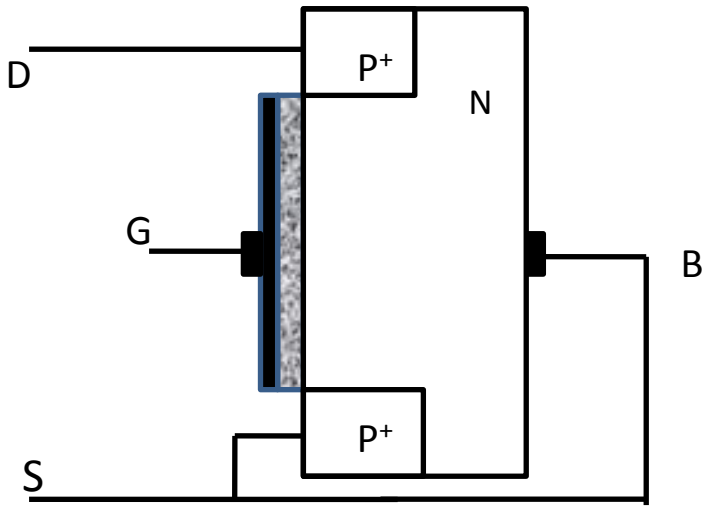
Salida en estado lógico bajo

$$P_E \approx \frac{1}{2}\frac{V_{DD}^2}{R_L}$$

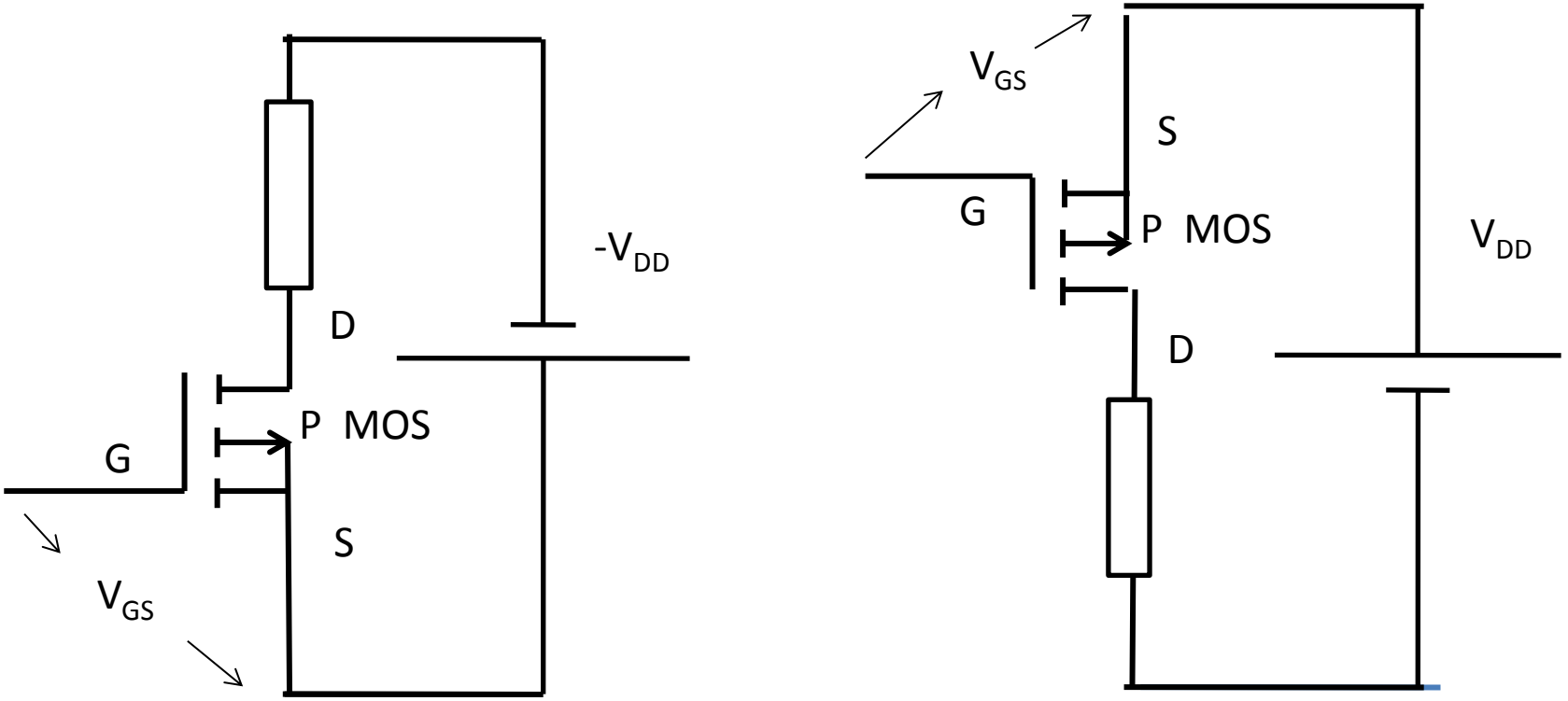
Inversor PMOS







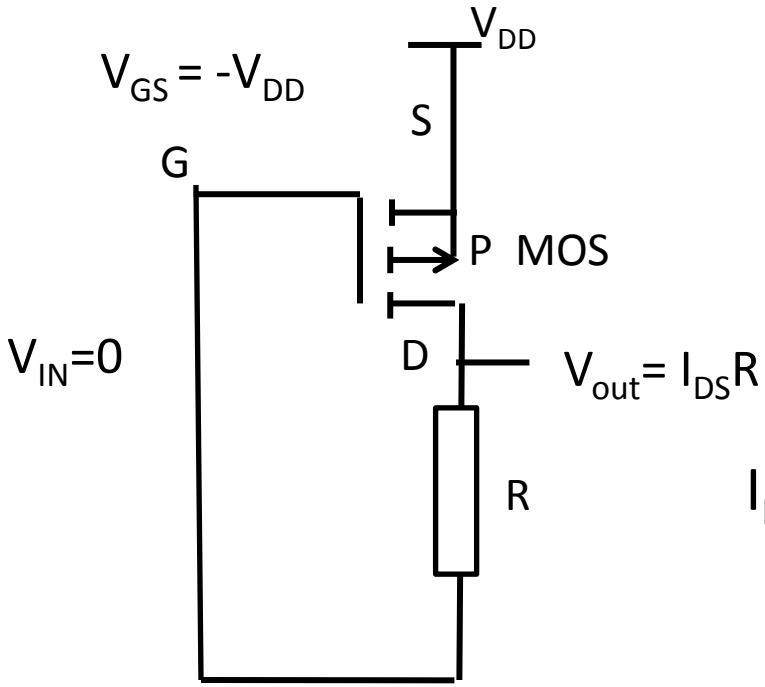
INVERSOR P MOS



INVERSOR P MOS

$V_{IN}=V_{DD}+V_{GS}$

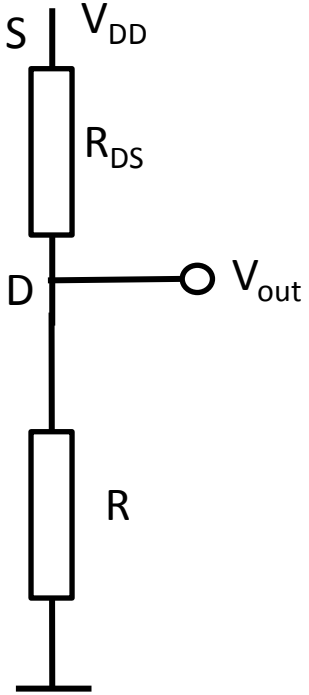
$$V_{out} = I_{DS} R$$



$|V_{TH}| < |V_{GS}|$

MOS → CONDUCE

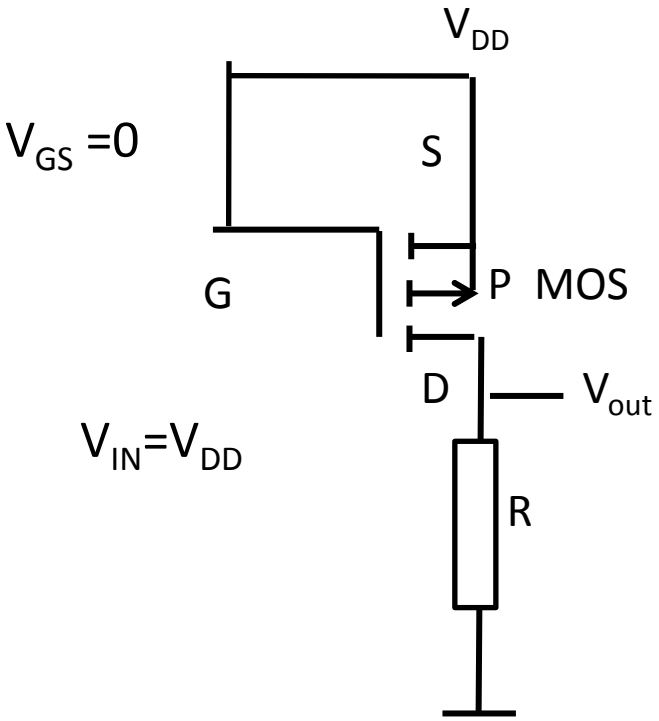
I_{DS} Óhmico o Saturado



INVERSOR P MOS

$V_{IN}=V_{DD}+V_{GS}$

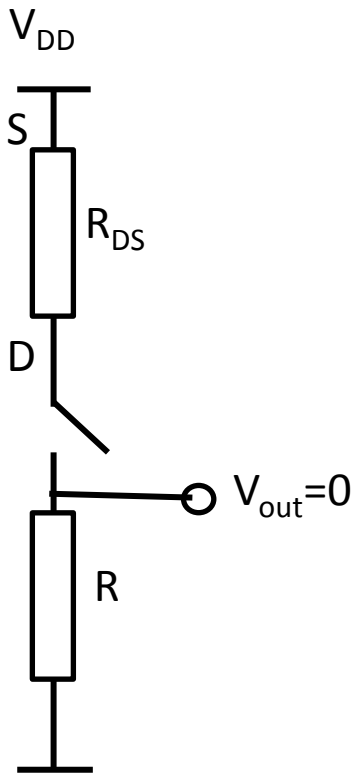
$V_{out} = 0$



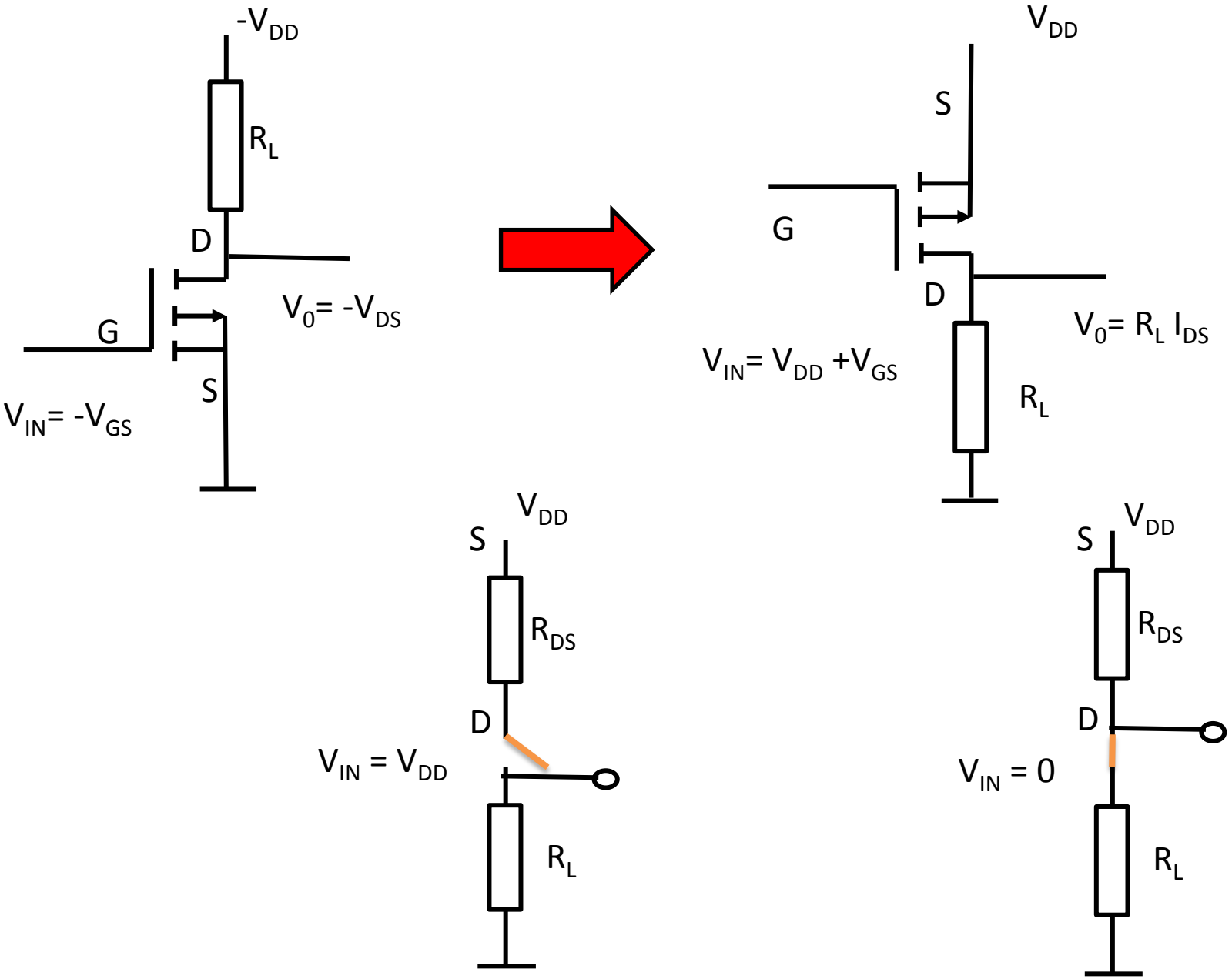
$|V_{TH}| > |V_{GS}|$

MOS → CORTADO

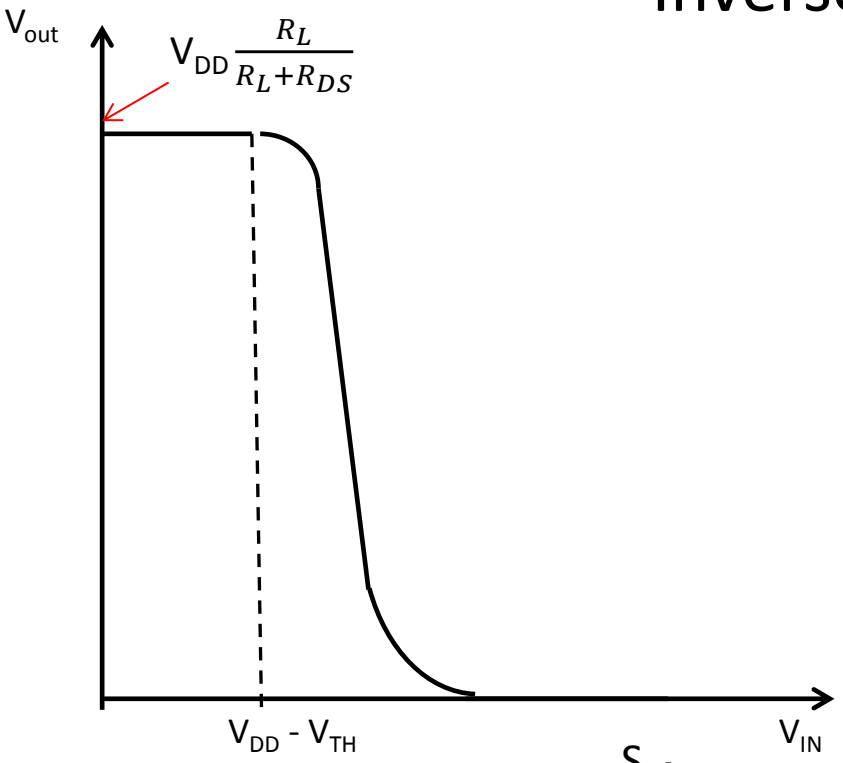
$V_{out} = 0$

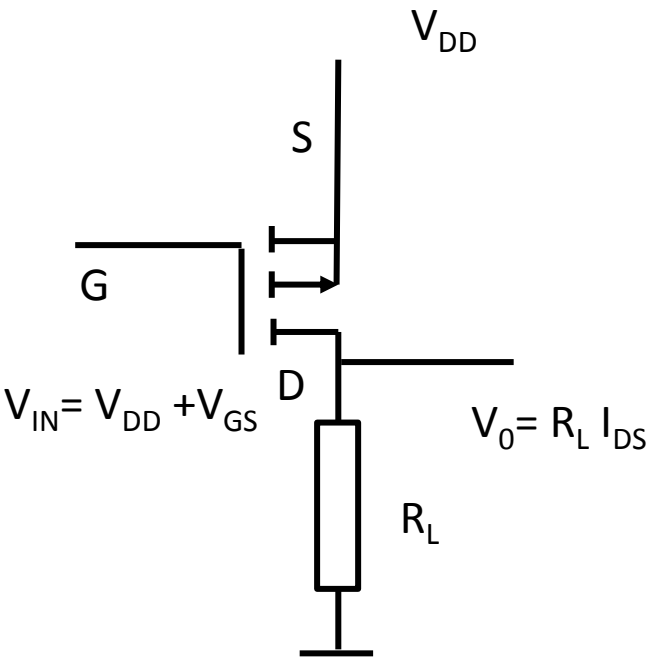


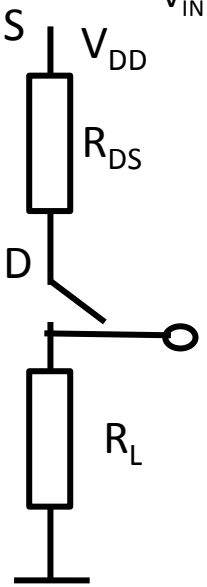
Inversor PMOS



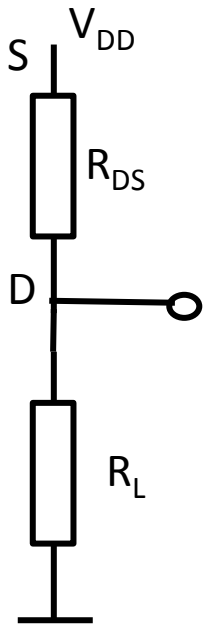
Inversor PMOS





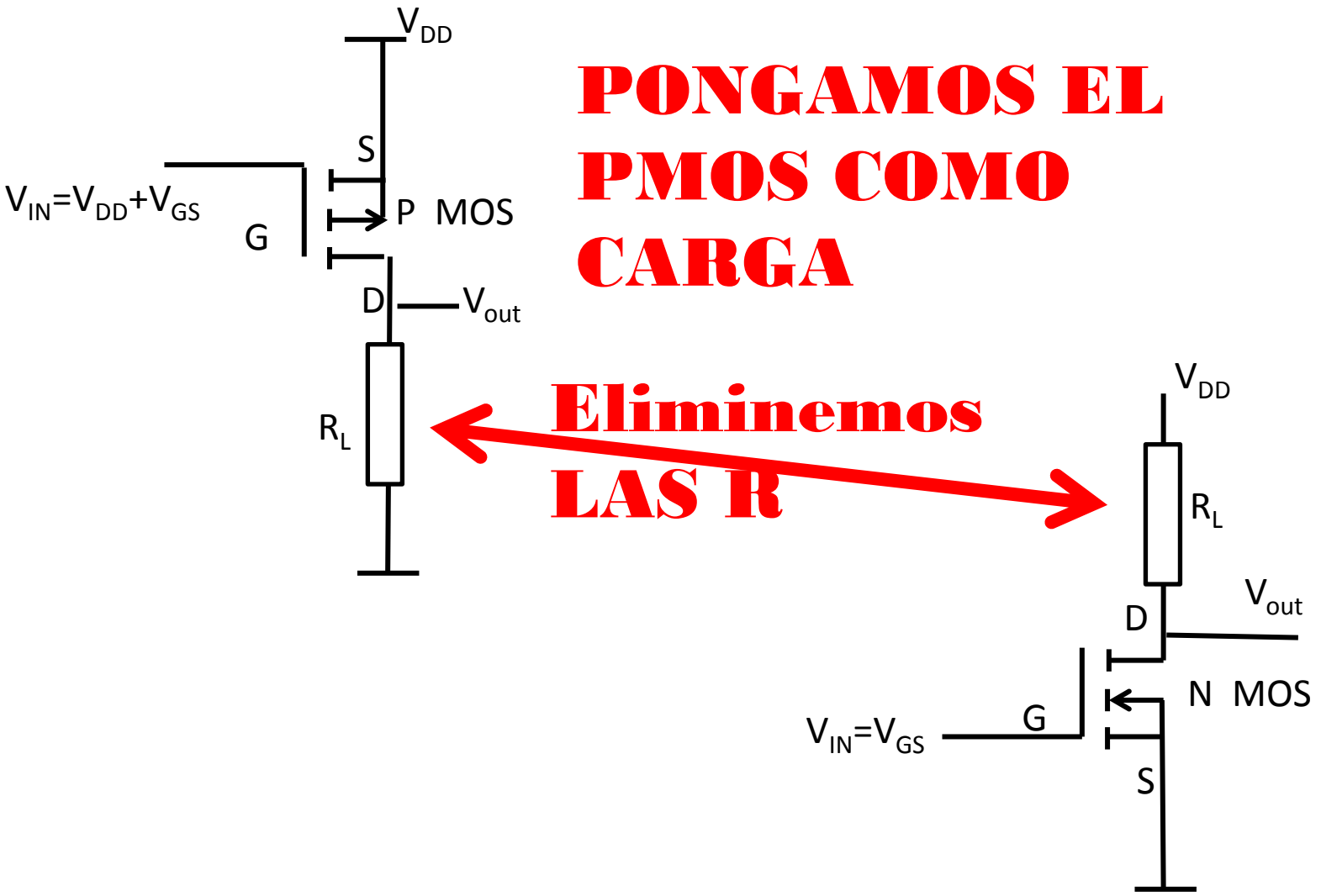


El valor de V_L de salida del inversor es 0 V

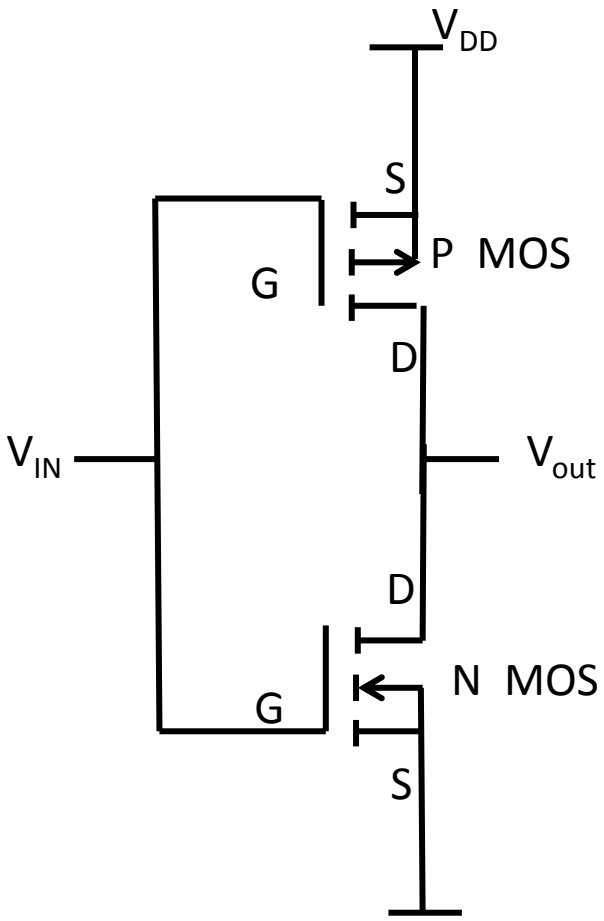


El valor de V_H de salida del inversor no es V_{DD}

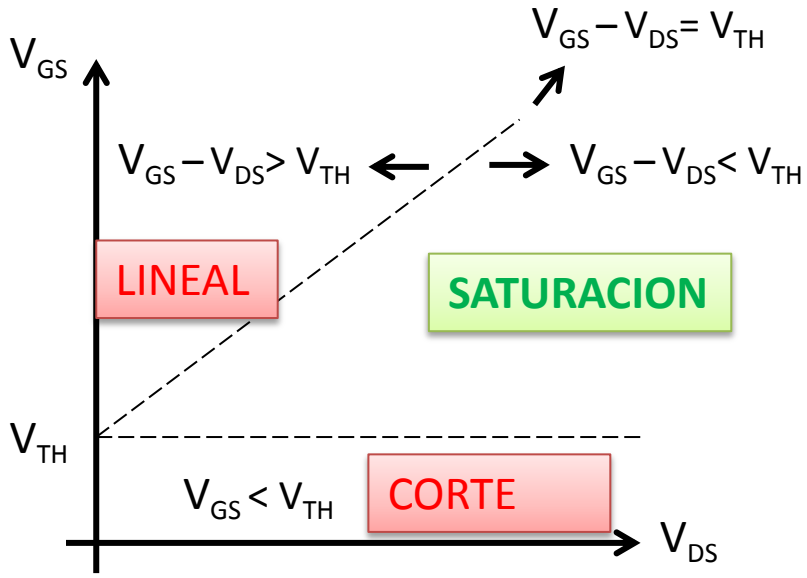
INVERSOR CMOS



INVERSOR C MOS

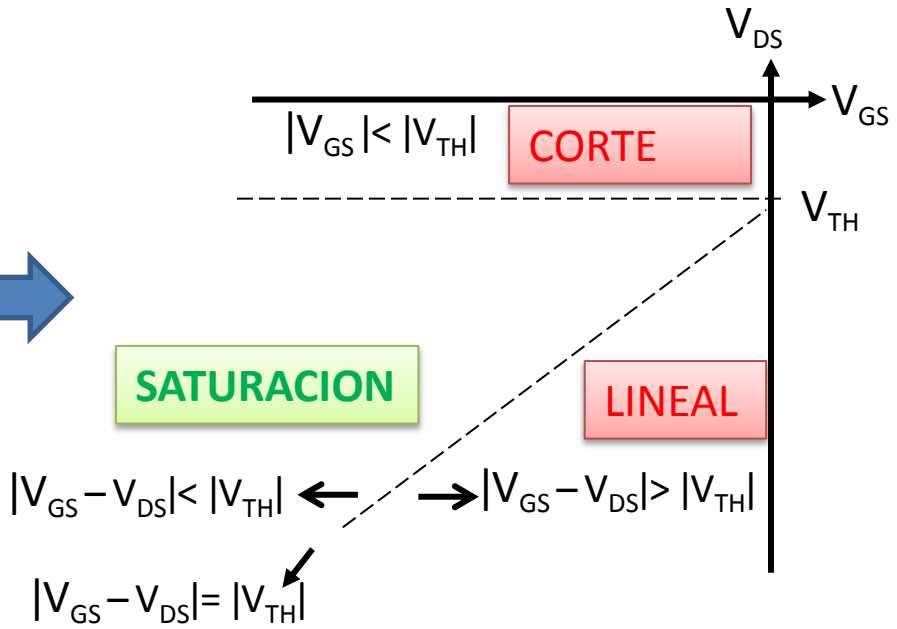


V_{GS} vs V_{DS}

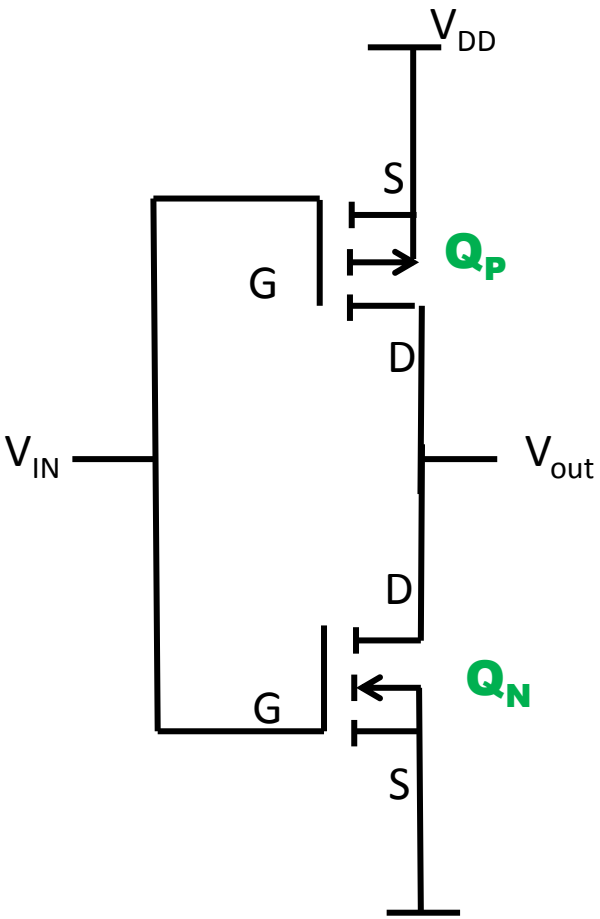


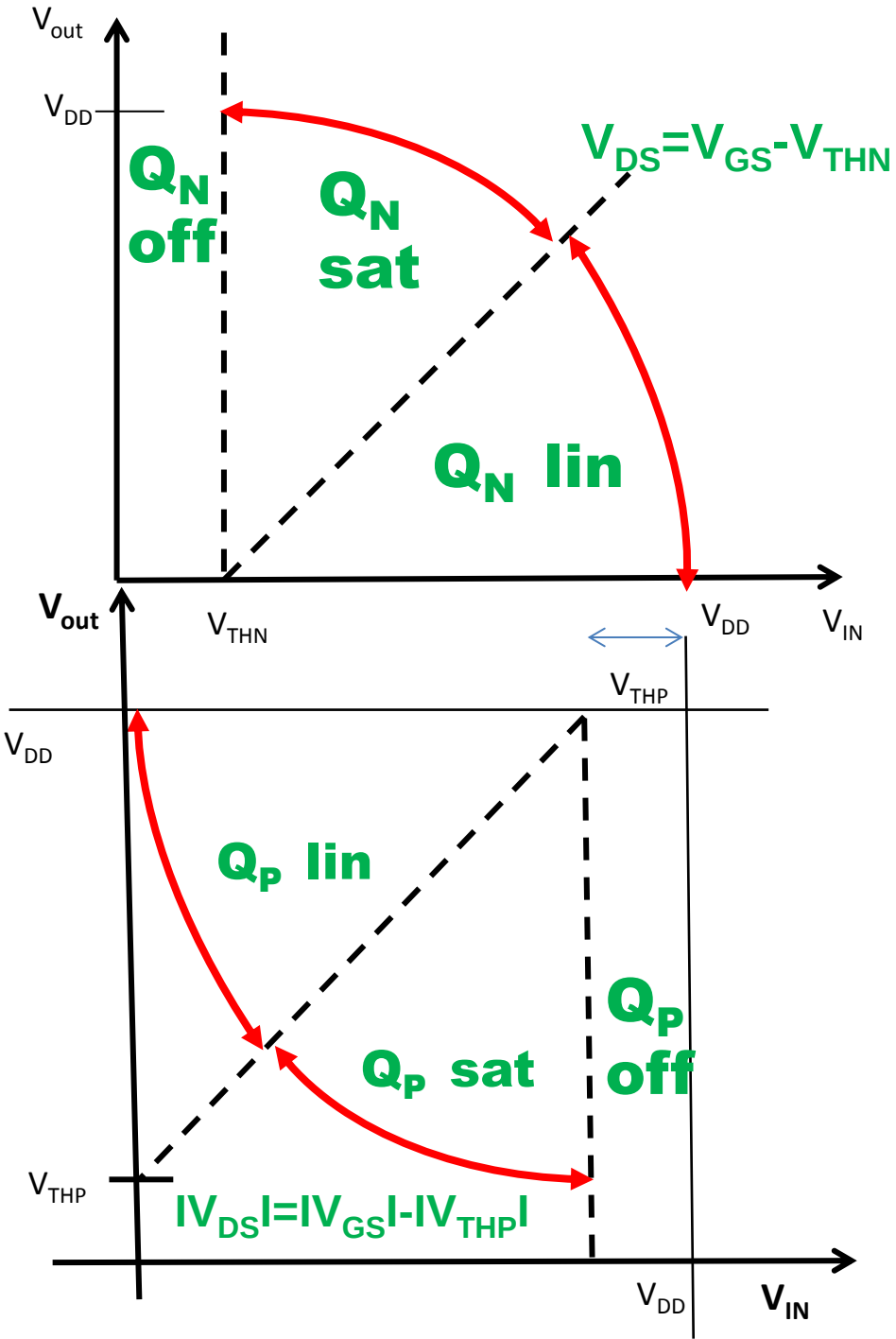
ENRIQUECIMIENTO CANAL N

ENRIQUECIMIENTO CANAL P

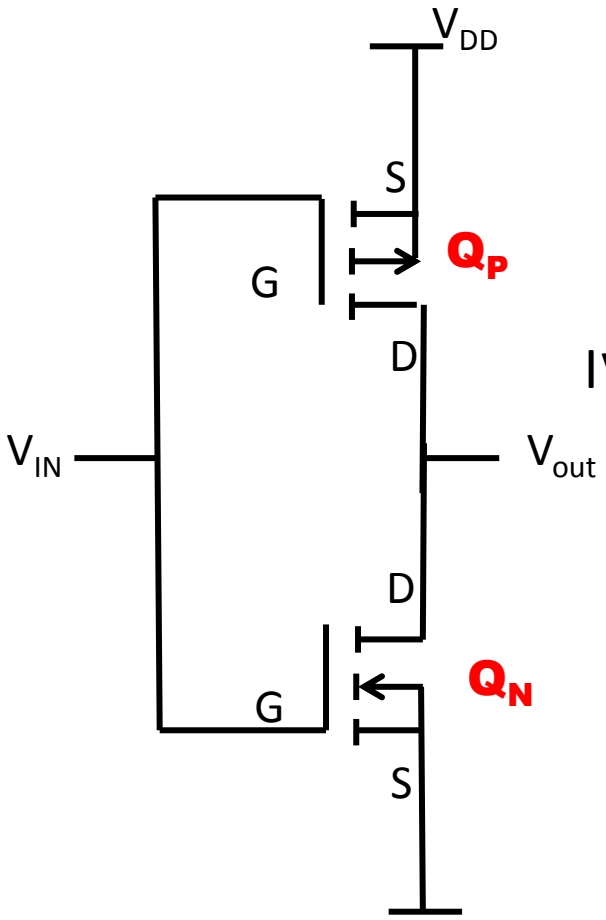


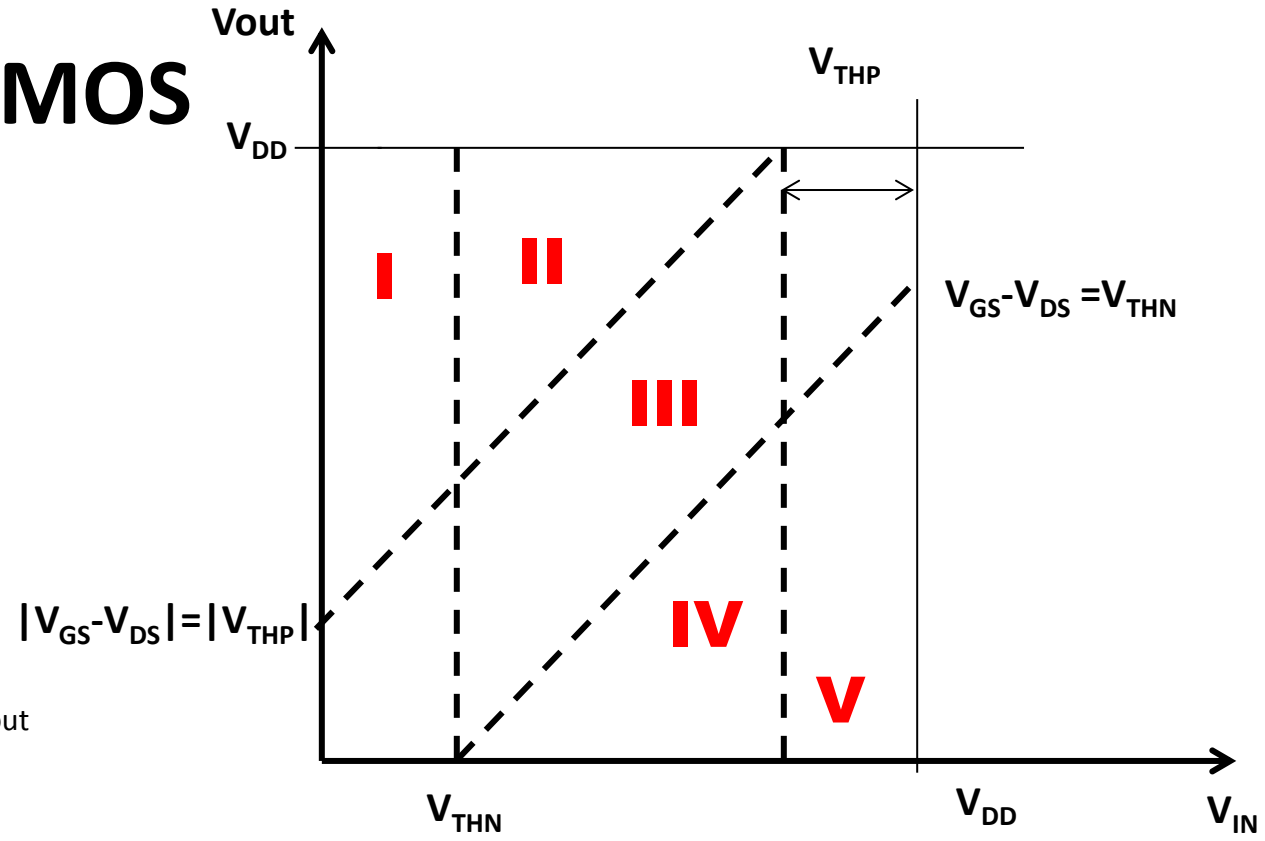
INVERSOR C MOS





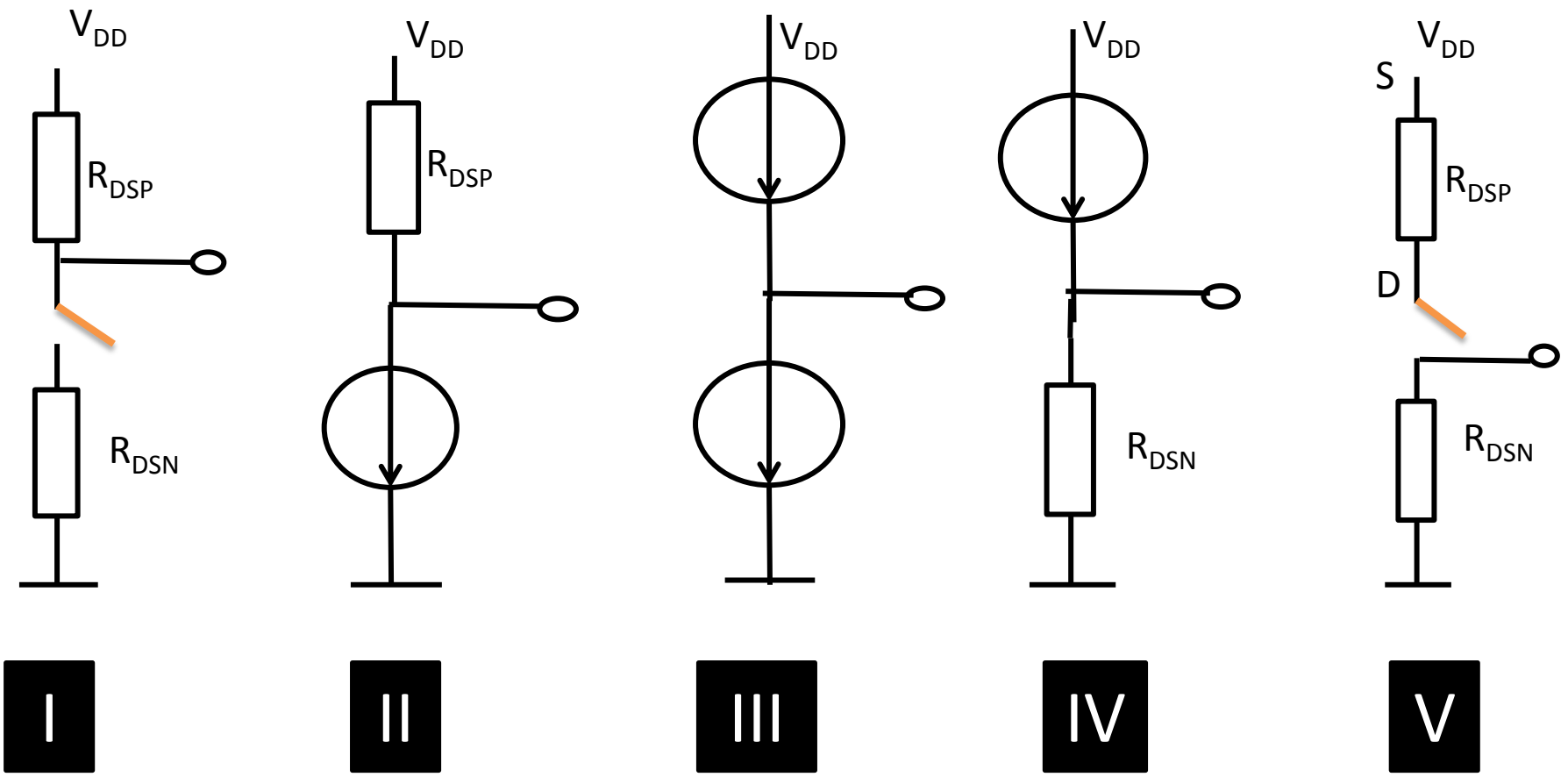
INVERSOR C MOS



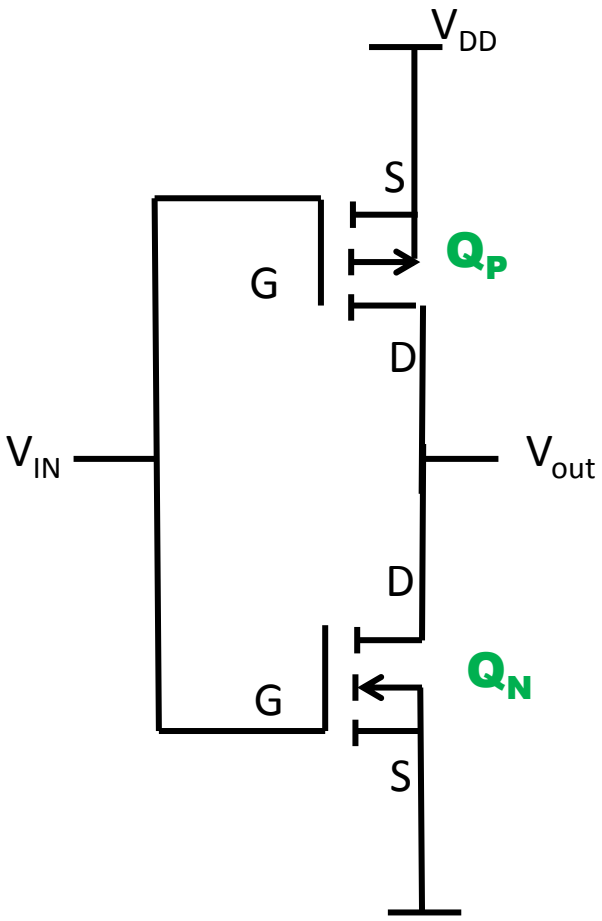


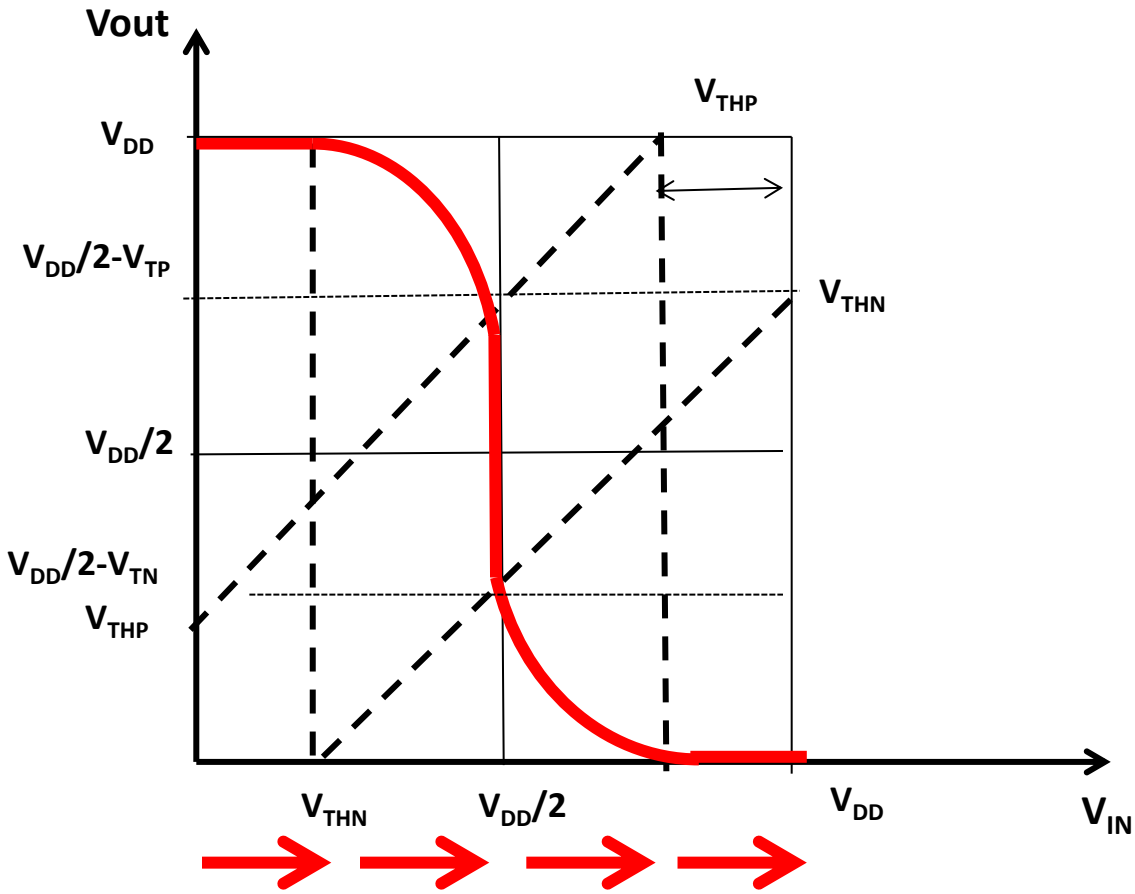
	Q_N	Q_P
I	off	lineal
II	satur	lineal
III	satur	satur
IV	lineal	satur
V	lineal	off

MODELOS SEGÚN ZONA DE OPERACION

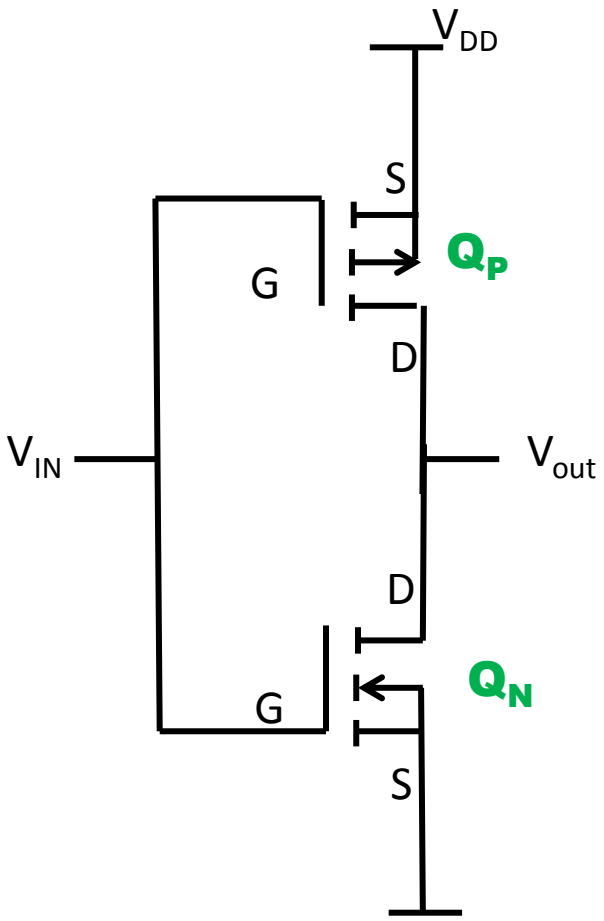


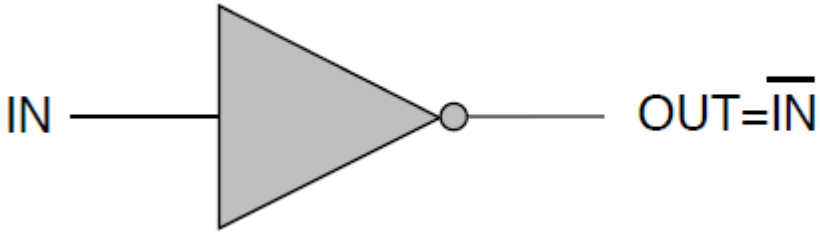
INVERSOR CMOS



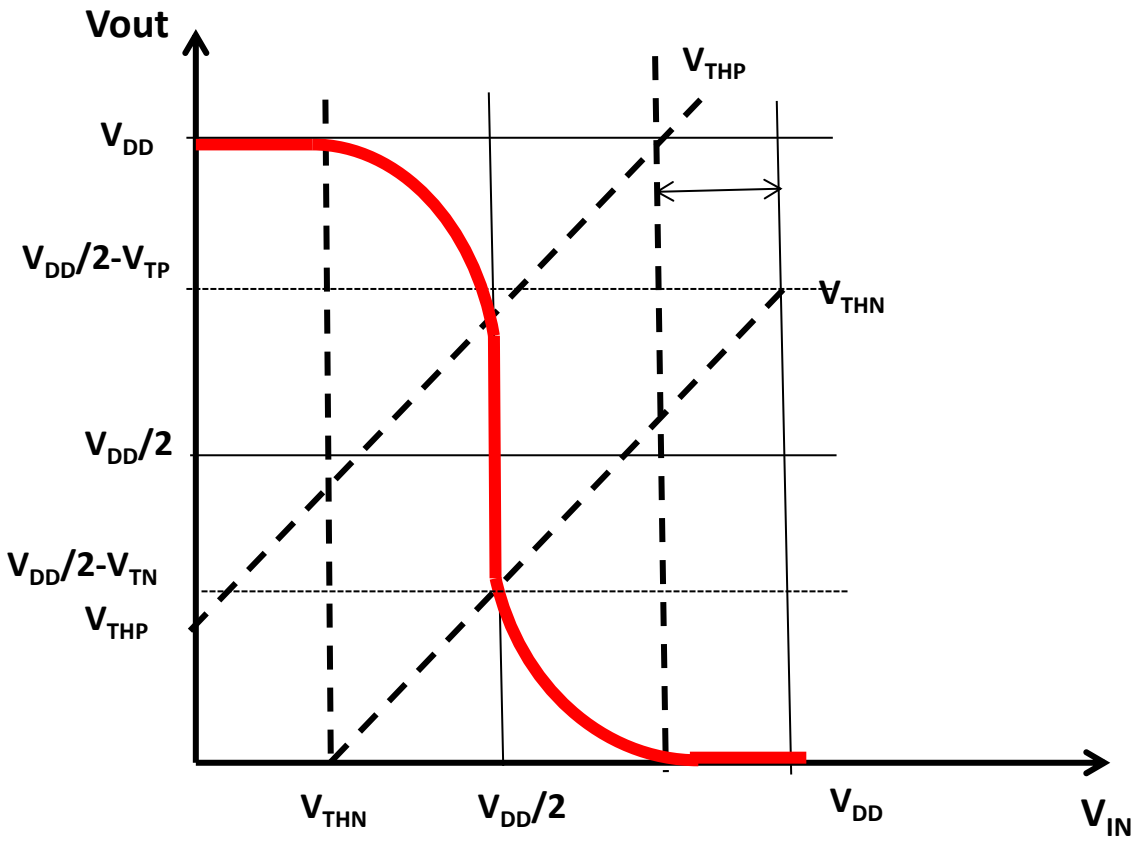


INVERSOR CMOS



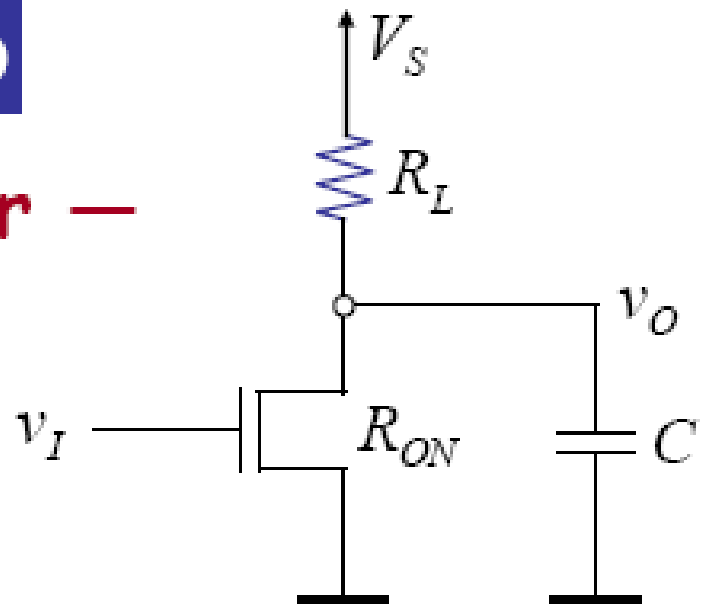


IN	OUT
0	1
1	0



Repaso

Inversor —



Entrada de onda cuadrada $T = \frac{1}{f}$

$$\overline{P} = \frac{V_S^{\,2}}{2R_L} + CV_S^{\,2} f$$

$\overline{P}_{ESTÁTICO}$ $\overline{P}_{DINÁMICO}$

$R_L >> R_{ON}$

$\frac{T}{2} >>$ " RC "

constante de tiempo

independiente de f.
el MOSFET está ON
la mitad del tiempo.

relacionado con el condensador
de conmutación.

Algunos números...

Un chip con 10^6 puertas cronometrando a 100 MHZ

$$C = 1f\,F$$
$$R_L = 10\,k\Omega$$
$$f = 100 \times 10^6$$
$$V_S = 5V$$

$$\overline{P} = 10^6 \left[\frac{25}{2 \times 10^4} + 10^{-15} \times 25 \times 100 \times 10^6 \right]$$

$$= 10^6 \; [1.25\ milivatios \; + \; 2.5\ microvatios]$$

¡problema!

$1.25KW!$ — debe deshacerse de esto

$2.5W$ — no está mal

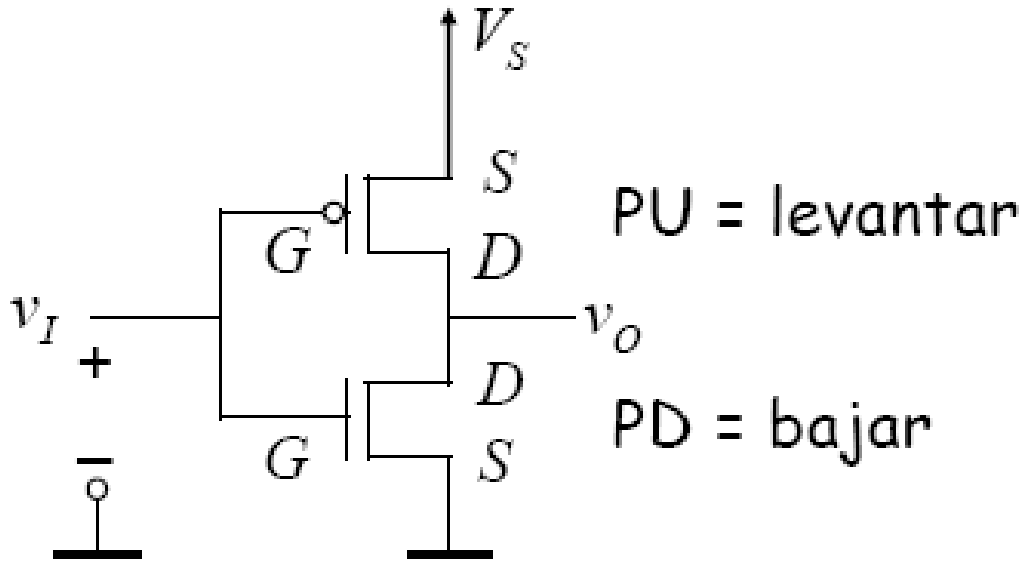
$\alpha\, V_S^{\,2}$

$\alpha\, f$

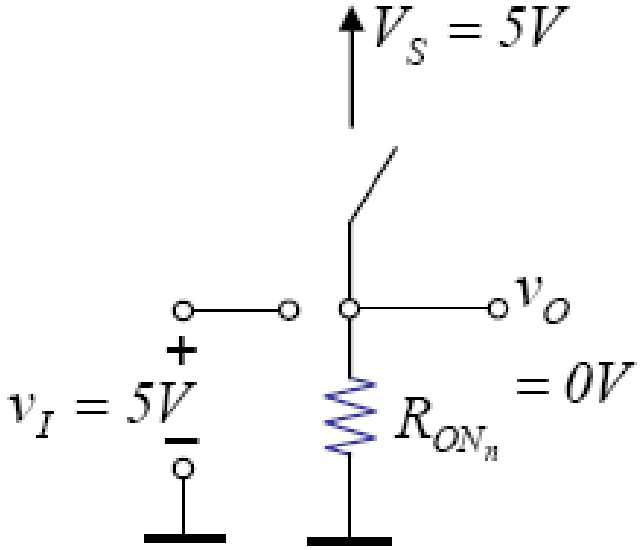
reduzca V_S

$5V \rightarrow 1V$

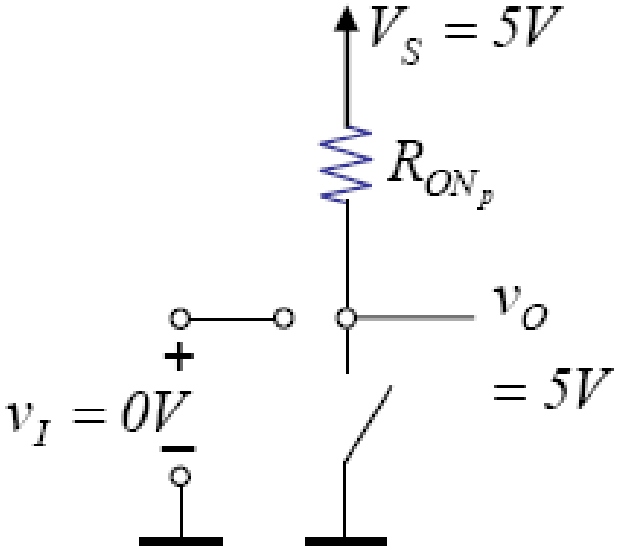
$2.5W \rightarrow 150\,mW$



$v_I = 5V$ (entrada alta)

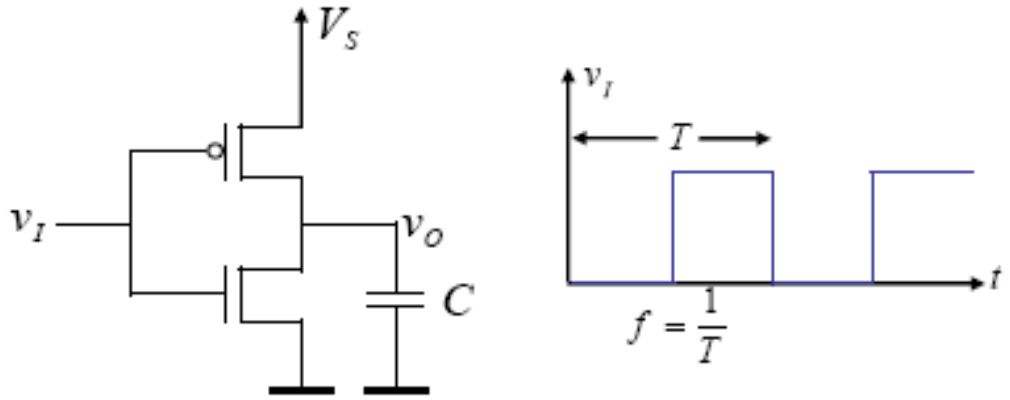


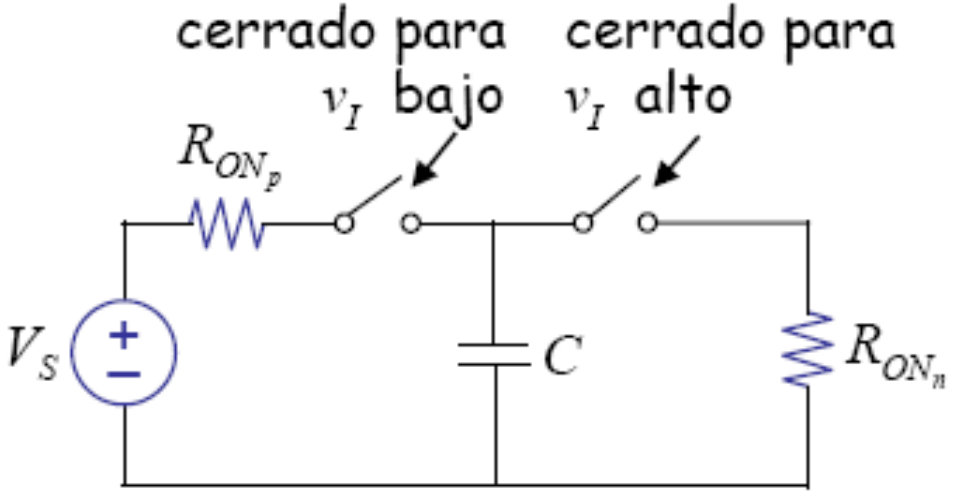
$v_I = 0V$ (entrada baja)



Clave: no hay camino desde V_S a GND no hay potencia estática

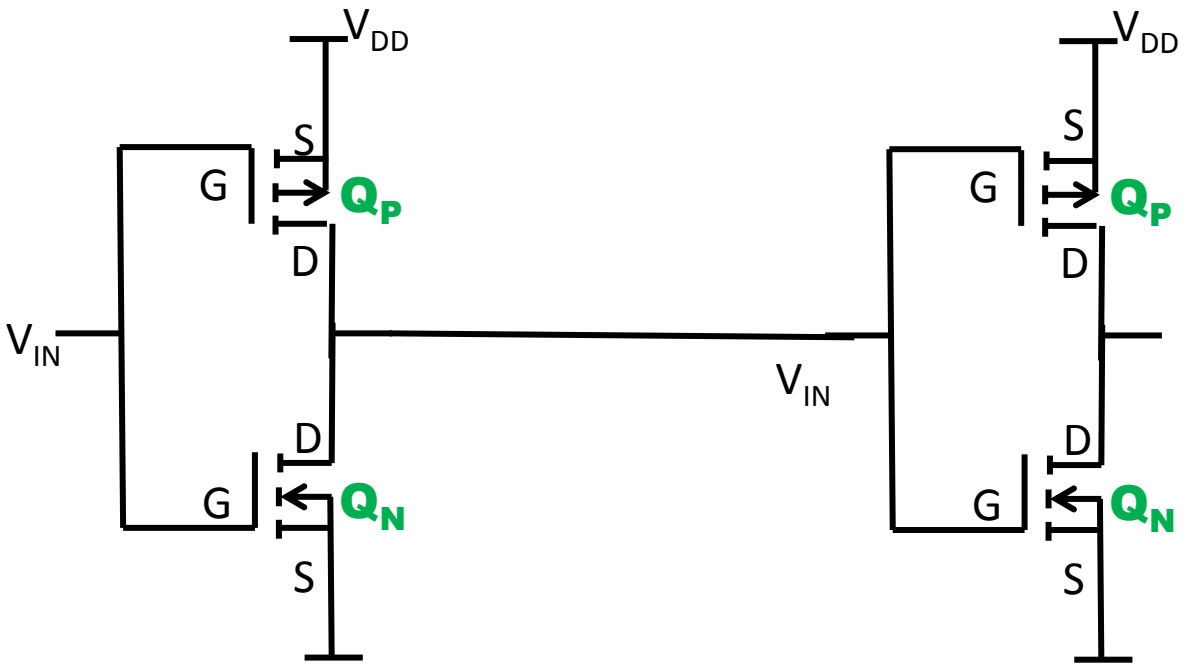
Calculemos $\overline{P}_{DINÁMICO}$





$$\overline{P} = CV_S^2 f$$

INVERSOR C MOS



La disipación de Potencia será $$P_{disipadapo\,rciclo} = C_L V_{DD}{}^2 f$$

Para nuestro ejemplo anterior—

$$C = 1fF,\ V_S = 5V,\ f = 100MHz,\ 1$$

$$\overline{P} = CV_S^2 f$$

$$= 10^{-15} \times 5^2 \times 100 \times 10^6$$

$$= 2.5\ \mu\text{vatios por puerta}$$

$$\overline{P} = 2.5\ \mu\text{vatios para el chip de puerta } 10^6$$

Puertas	f	$\overline{P}$	
10^6	100 MHz	~2.5 vatios	¿Pentium?
2×10^6	300 MHz	~15 vatios	¿PII?
2×10^6	600 MHz	~30 vatios	¿PII?
8×10^6	1.2 GHz	~240 vatios	¿PIII?
25×10^6	3 GHz	~1875 vatios	¿PIV?

"deje todo lo demás igual"

Cómo reducir potencia

Ⓐ V_S 5V → 3V → 1.8V → 1.5V

~PIV → 170 vatios → mejor, pero alto

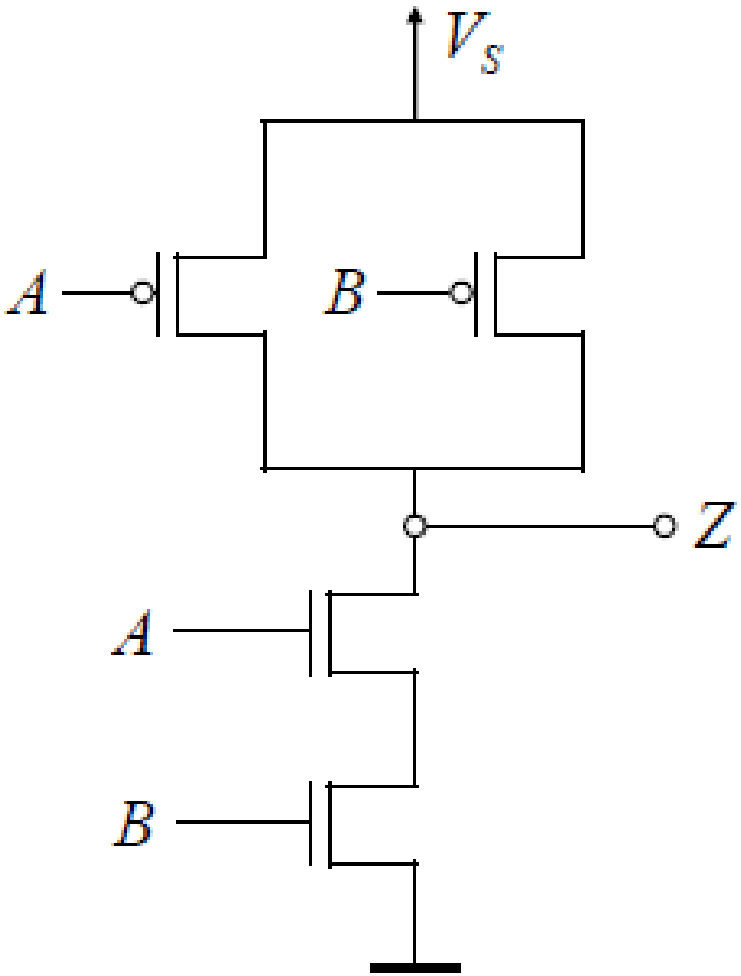
y utilice un disipador de calor grande

Ⓑ Desconecte el reloj cuando no se esté utilizando.

Ⓒ Cambie V_S según las necesidades.

LOGICA CMOS

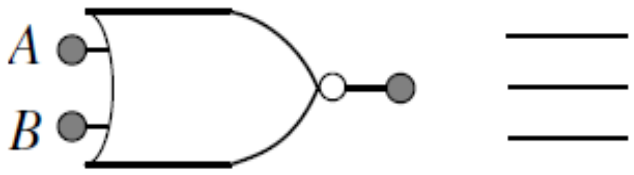
COMPUERTA NAND

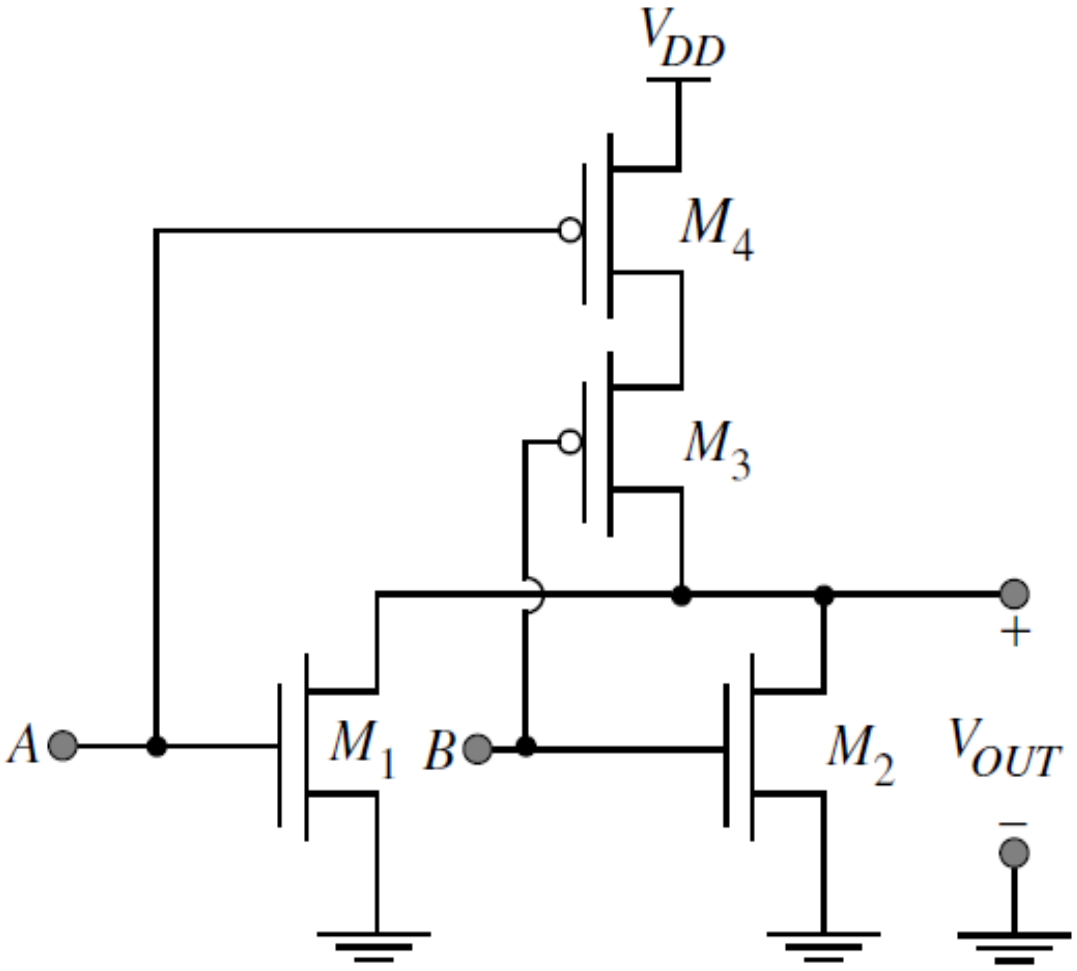


A	B	Z
0	0	1
0	1	1
1	0	1
1	1	0

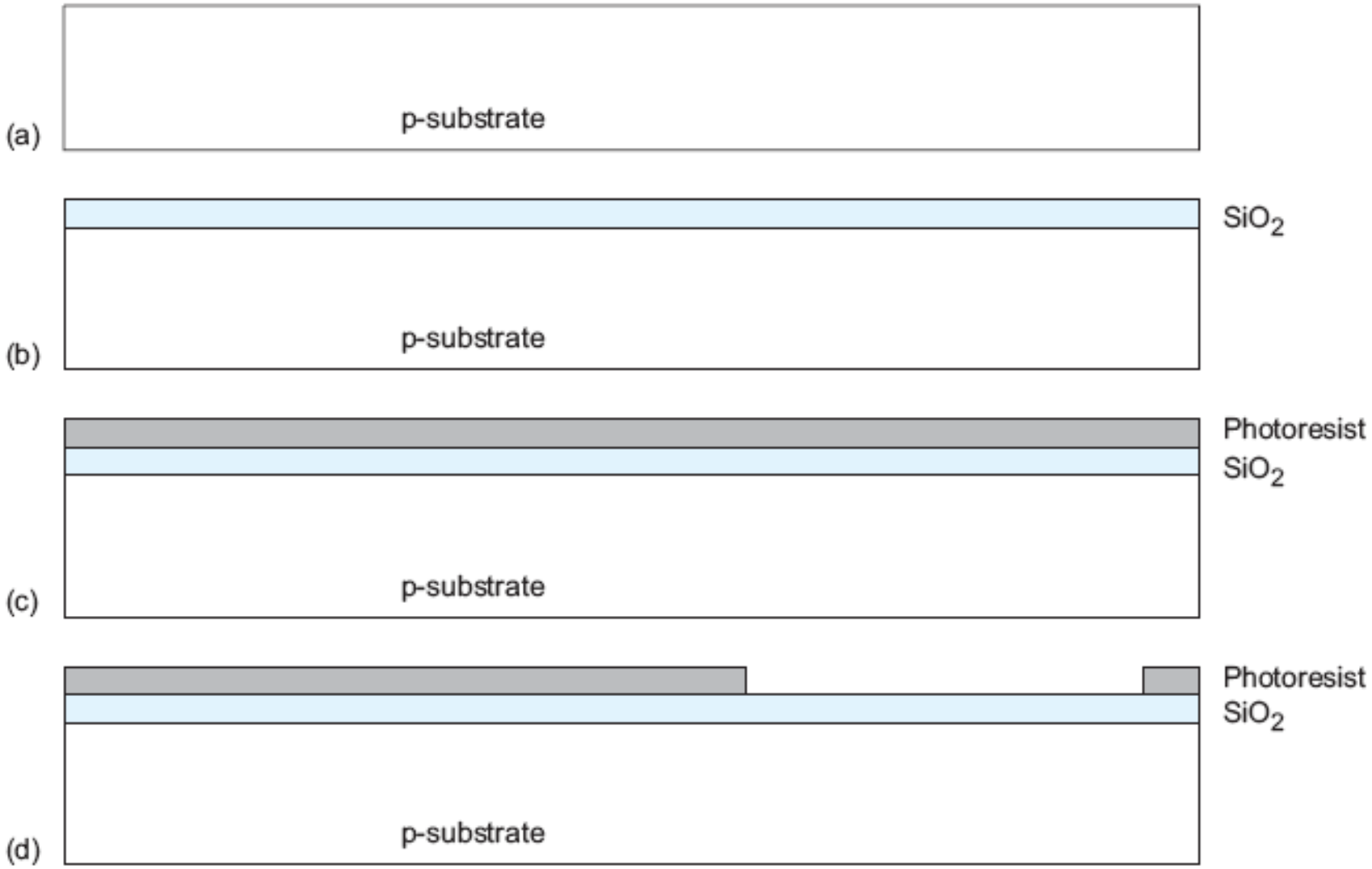
LOGICA CMOS

COMPUERTA NOR

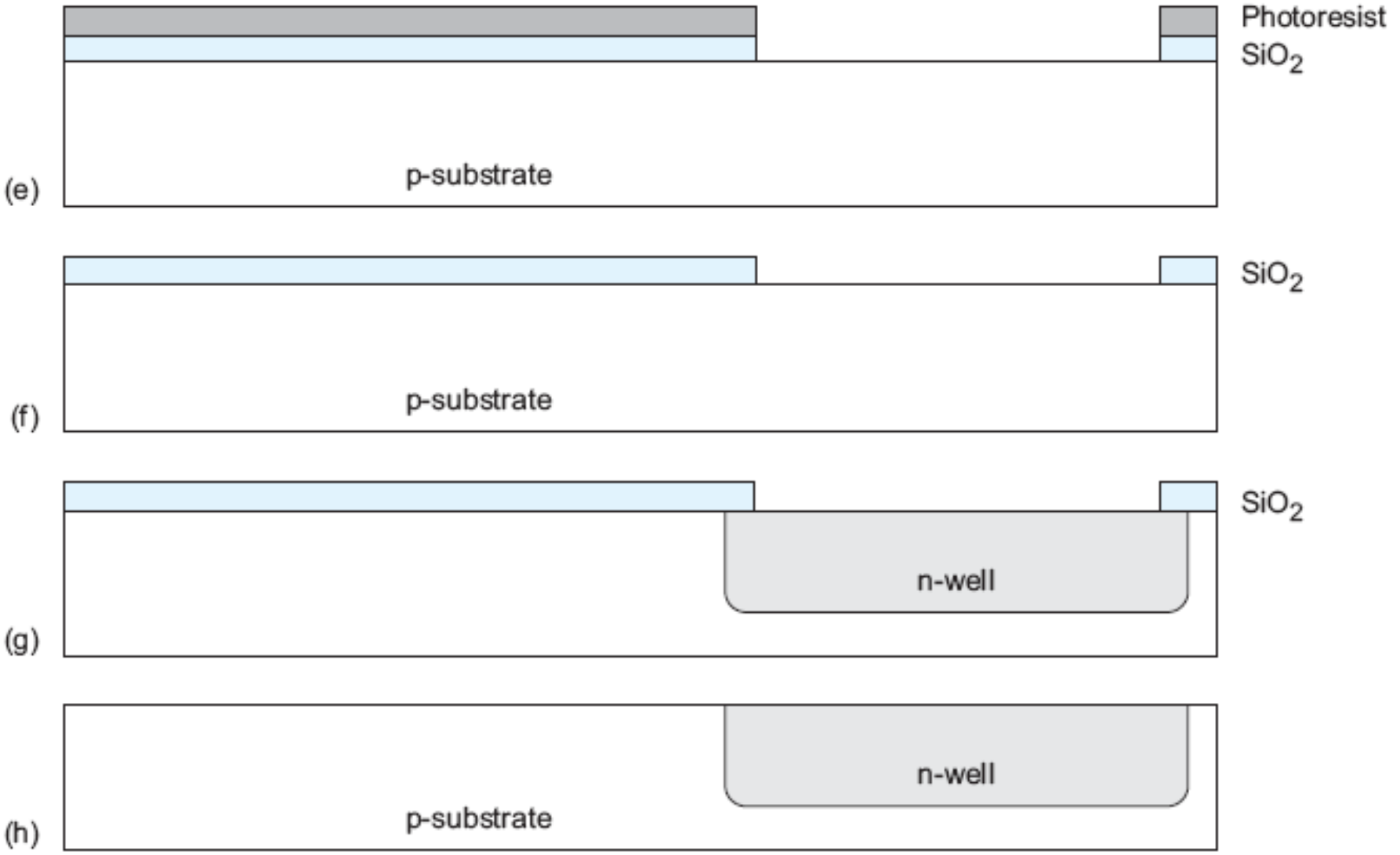




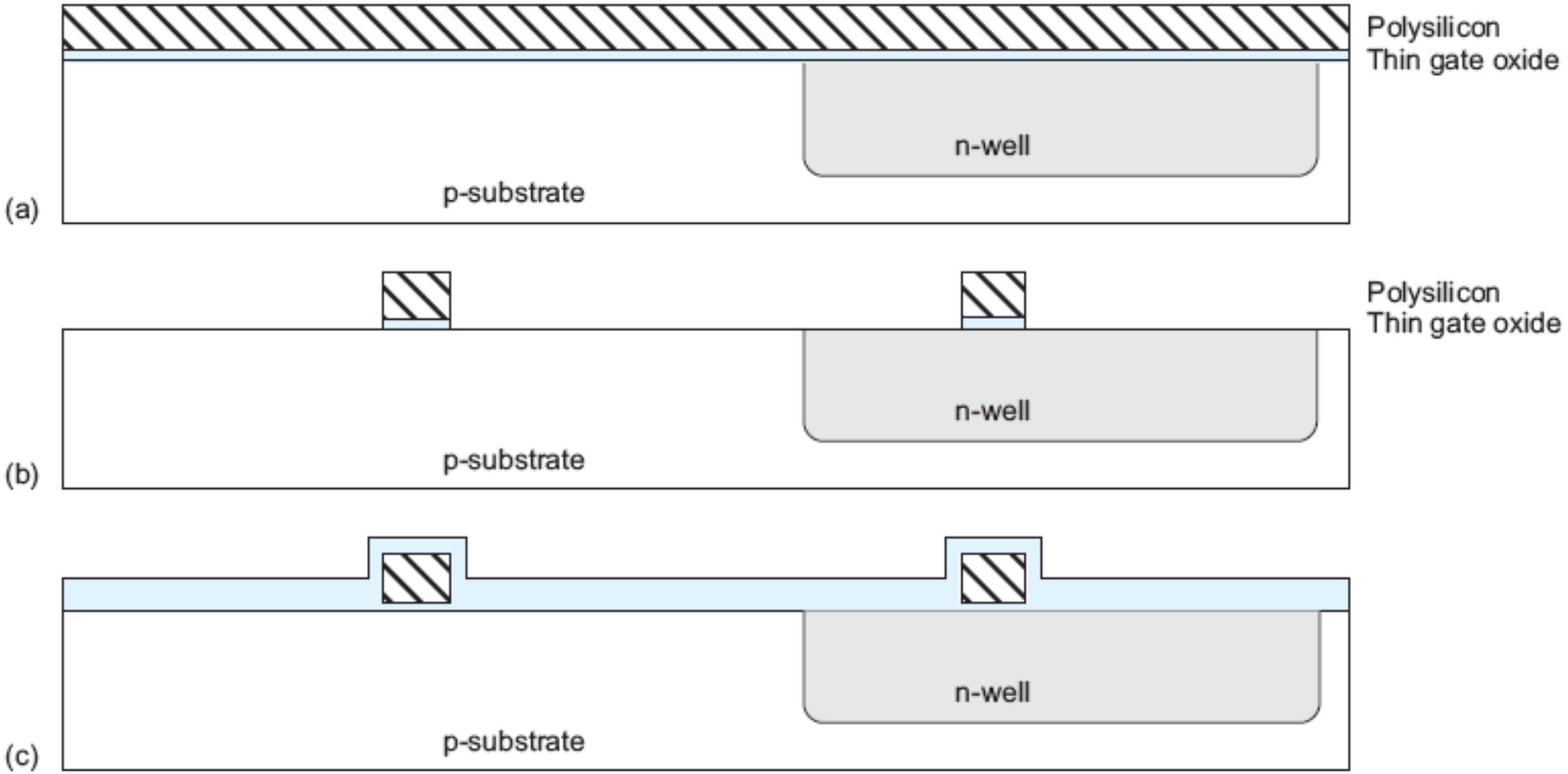
Fabricación de un inversor CMOS
I



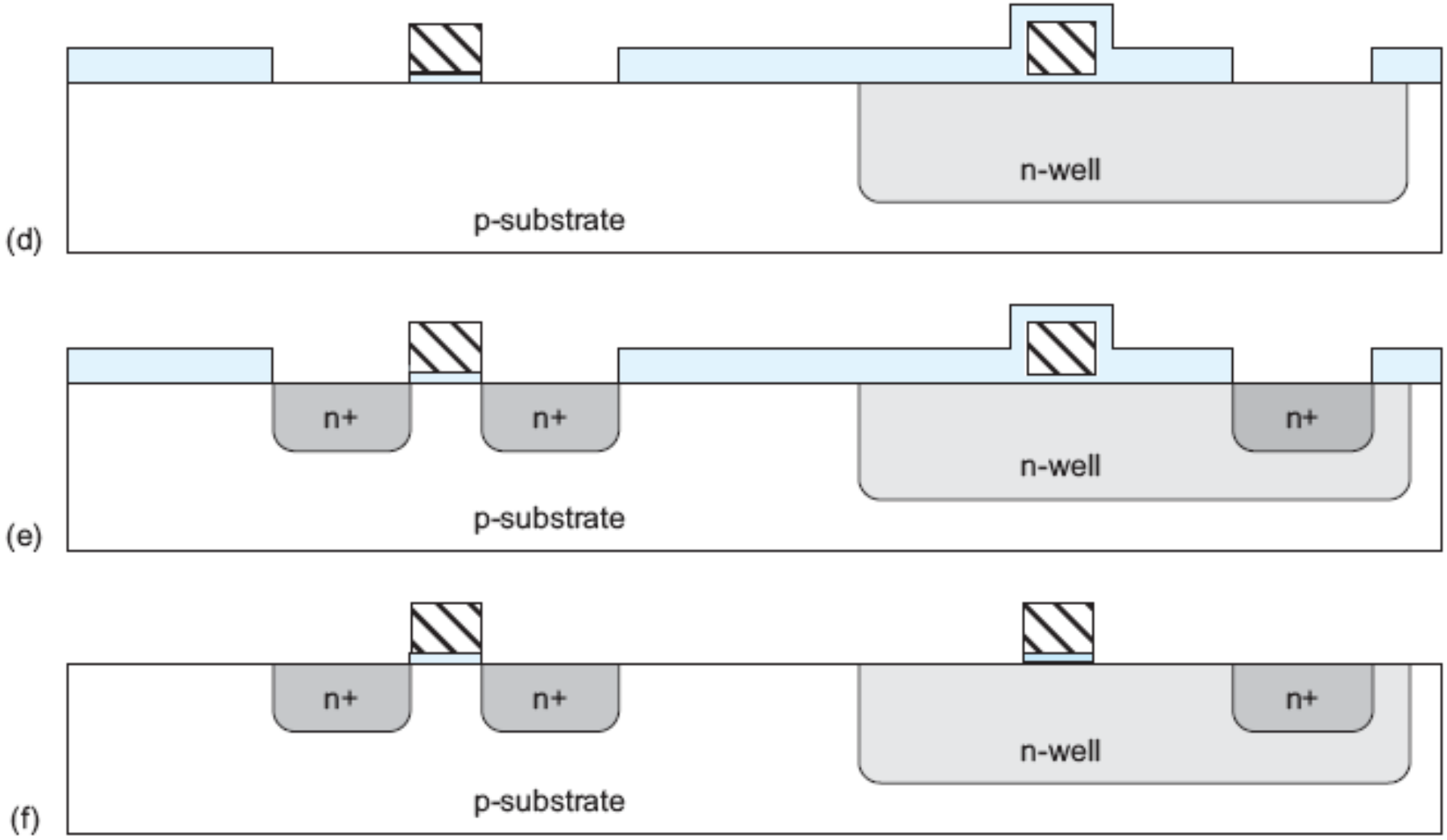
Fabricación de un inversor CMOS
II



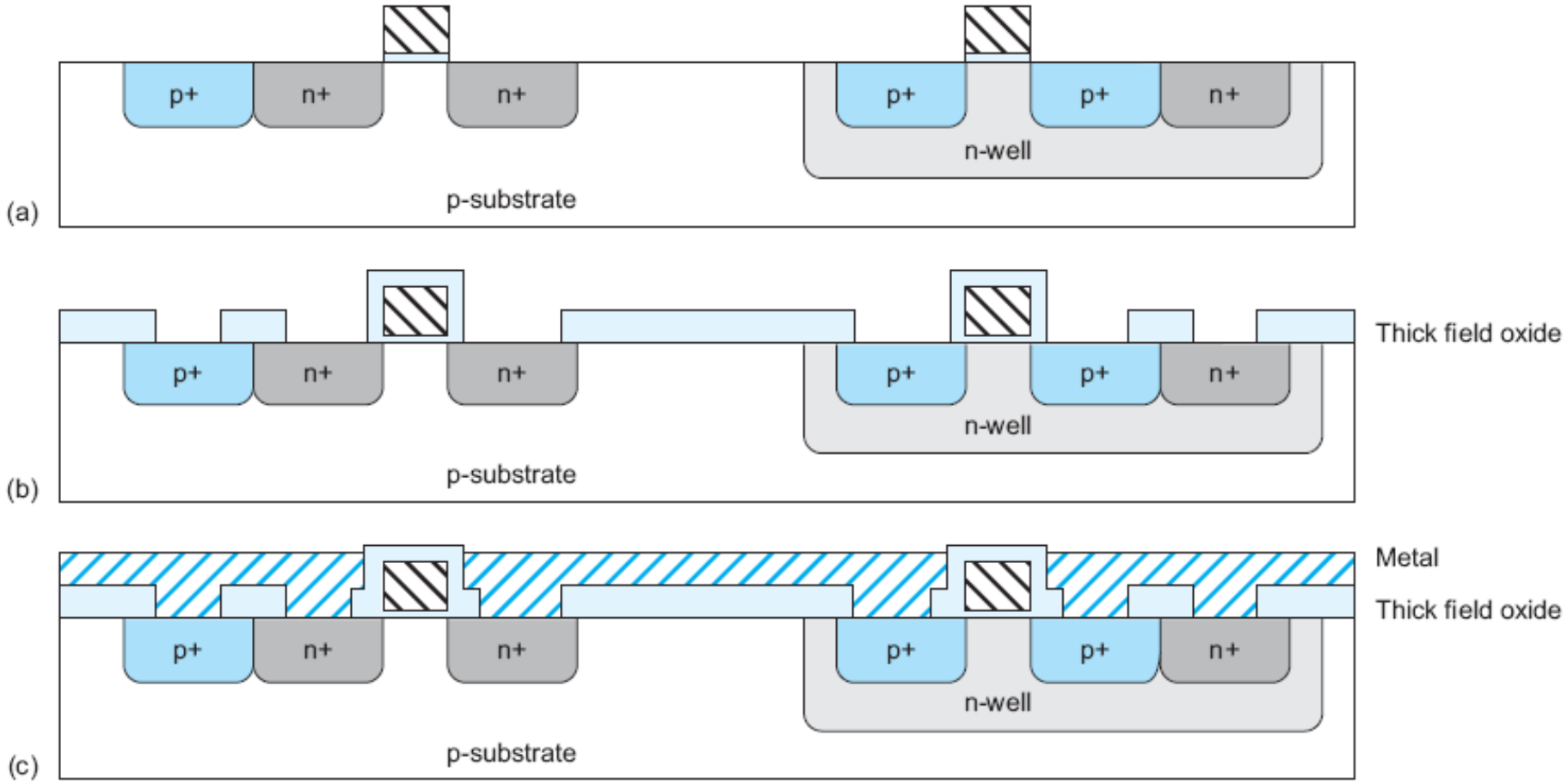
Fabricación de un inversor CMOS III



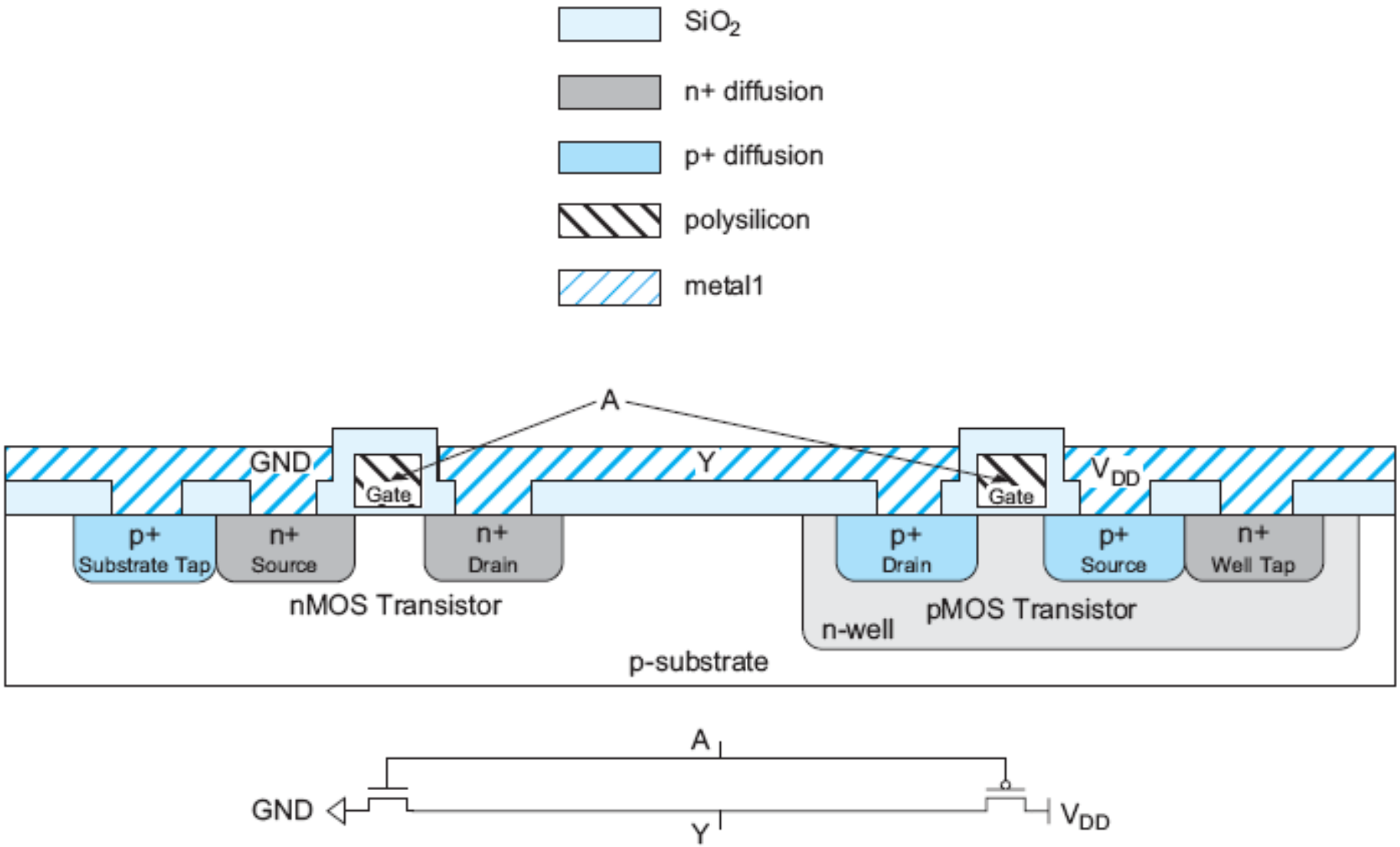
Fabricación de un inversor CMOS



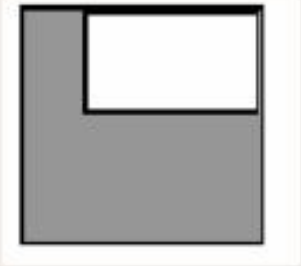
Fabricación de un inversor CMOS
IV

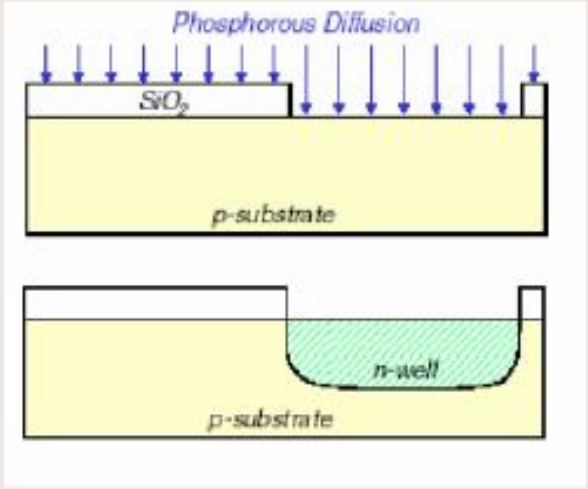


Corte transversal de un inversor CMOS



Mascara para eliminar SiO_2

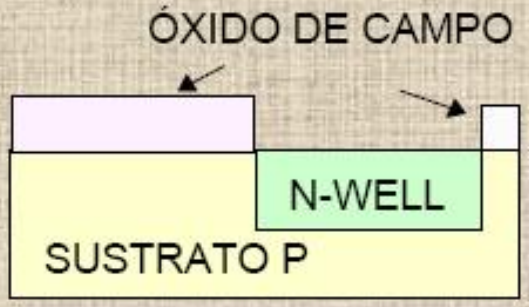


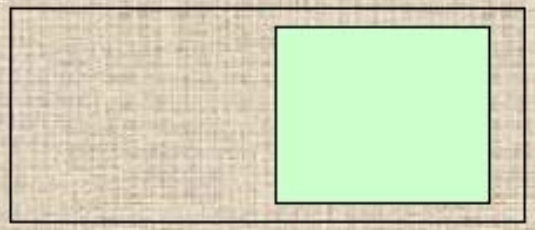


Máscara 1

Difusión de pozo

Pozo

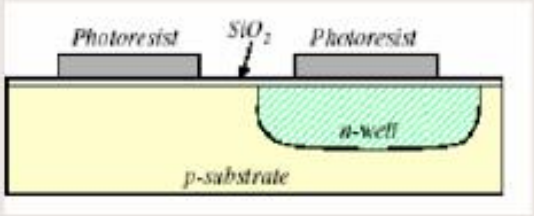


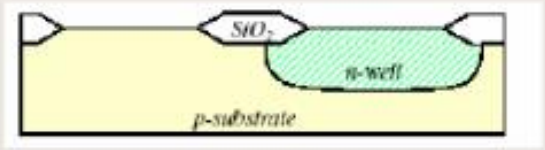


Máscara 2

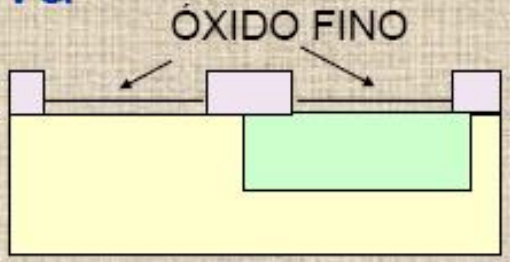
Definición de áreas activas

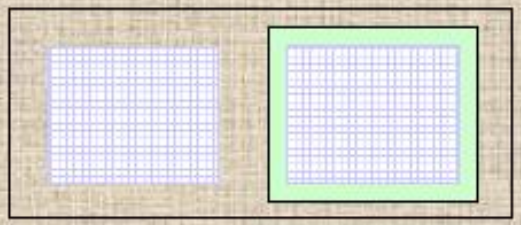
Define las regiones activas donde se van a colocar los dispositivos



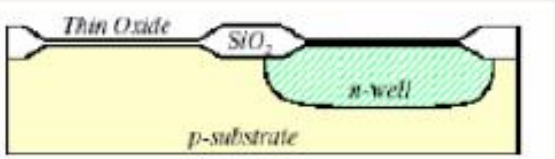


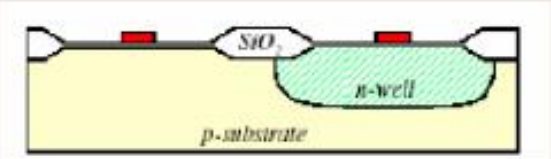
Área activa

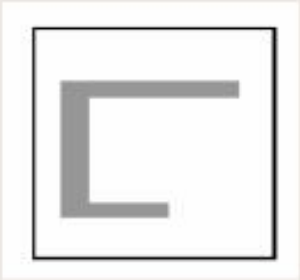




Se deposita el polisilicio de puerta



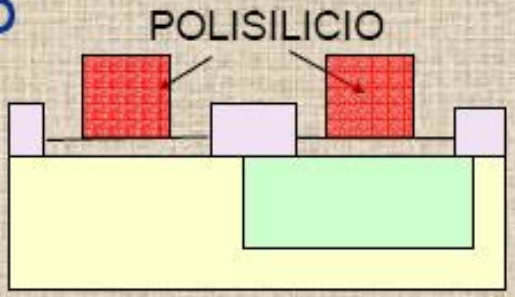


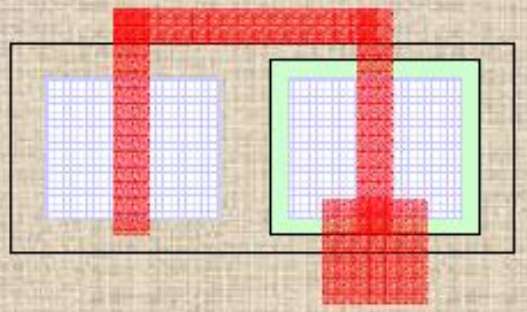


Máscara 3

Definición de las puertas

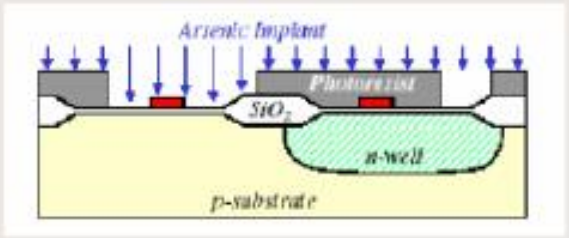
Polisilicio

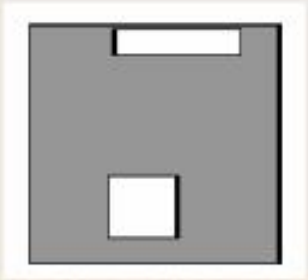


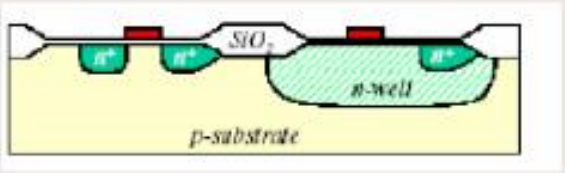


Máscara 4

Se crea la fuente y el drenador de los dispositivos n

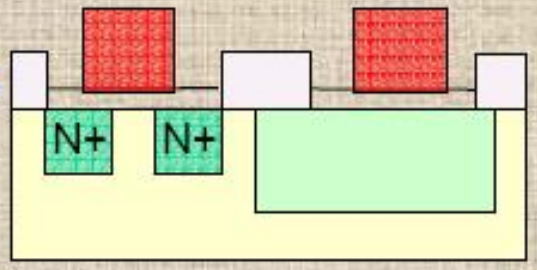


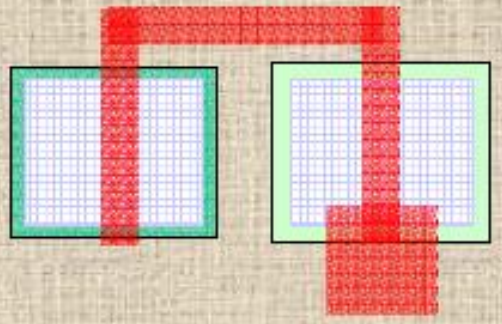




Difusión n+
MOS canal N

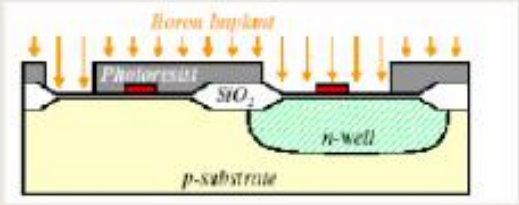
Implante N+

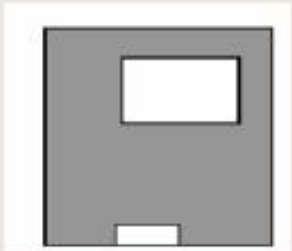


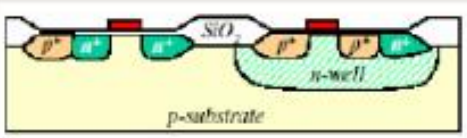


Máscara 5

Se crea la fuente y el drenador de los dispositivos p

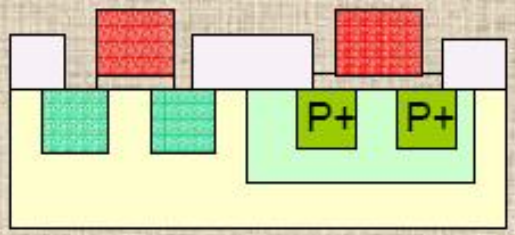


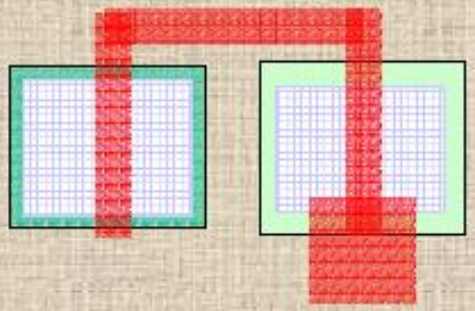




Difusión p+
MOS canal P

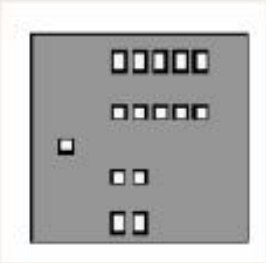
Implante P+

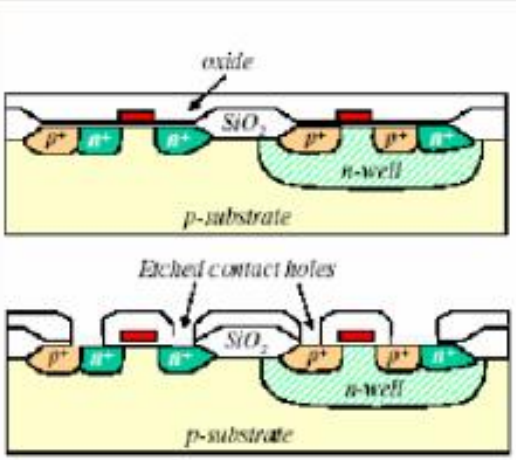




Máscara 6

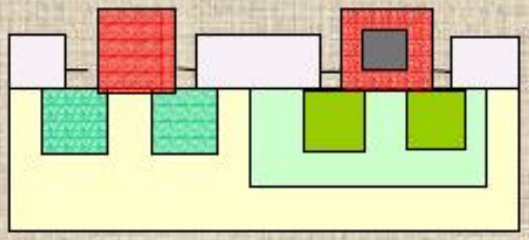
Determina las posiciones donde van los contactos

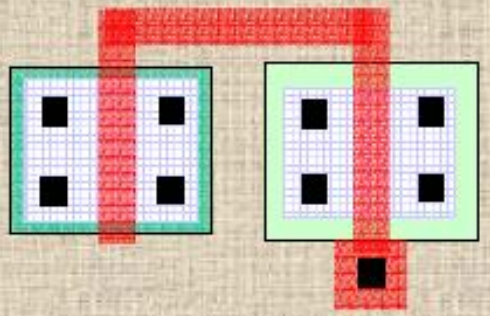




Perforaciones de contacto

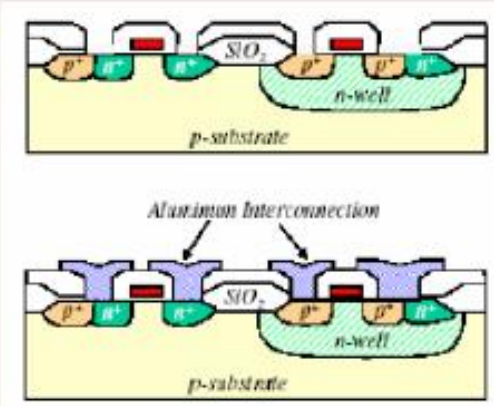
Contactos



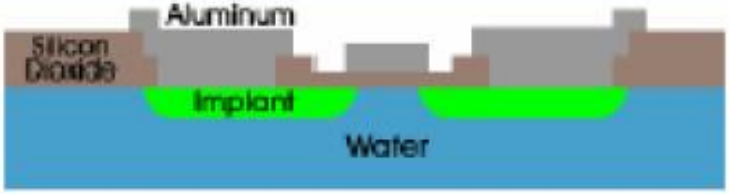


Máscara 7

Determina las posiciones donde van las interconexiones

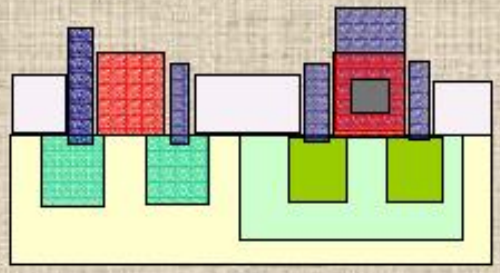


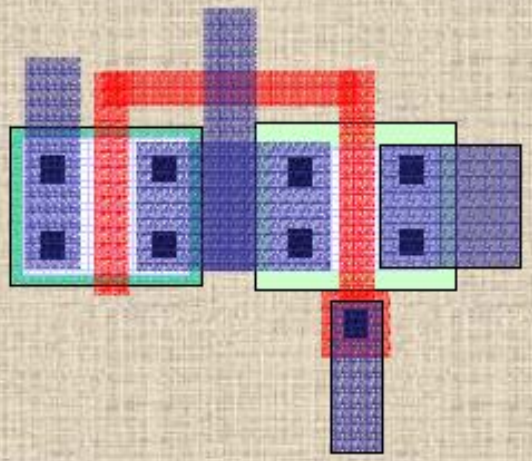
Metalización



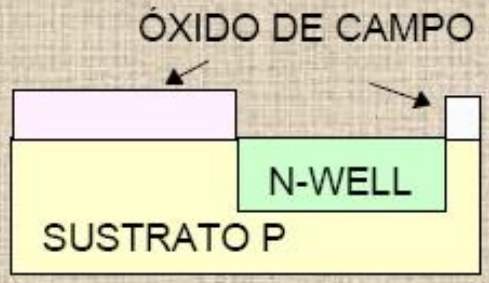
Metal Deposition

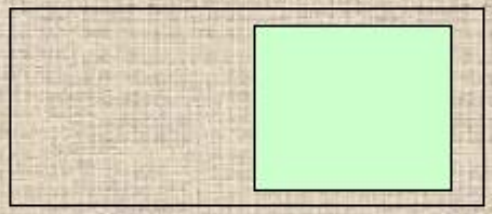
Metal



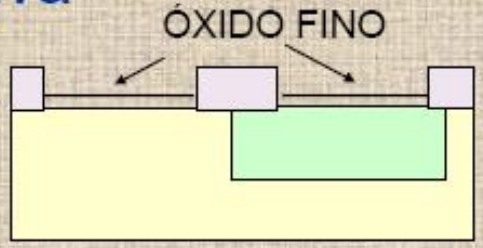


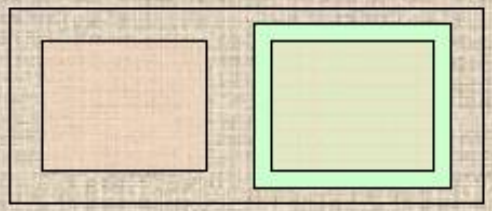
Pozo



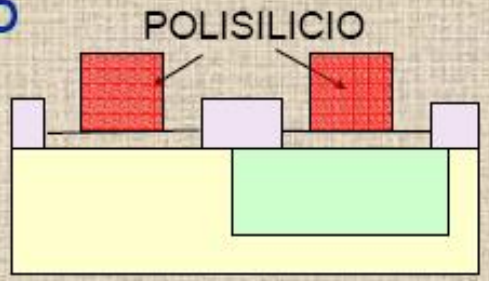


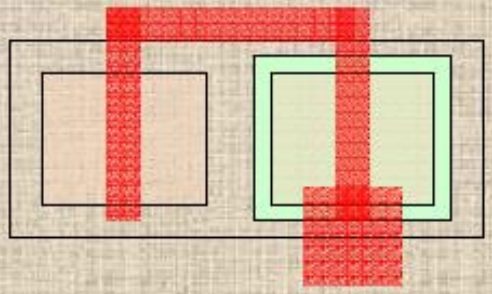
Área activa



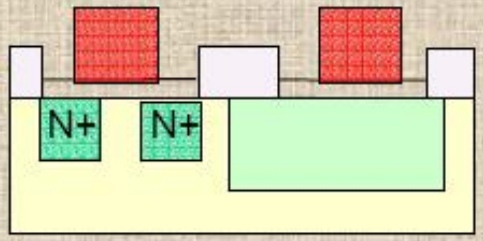


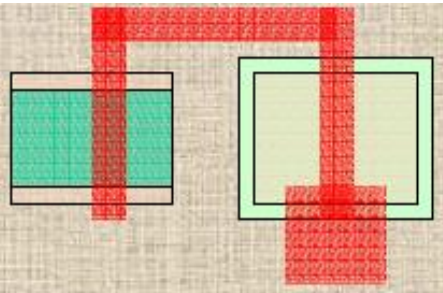
Polisilicio



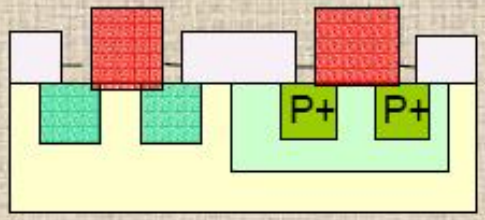


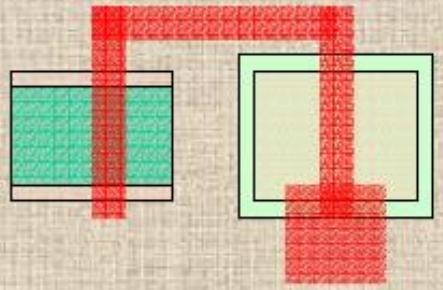
Implante N+



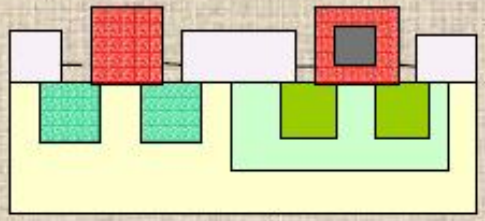


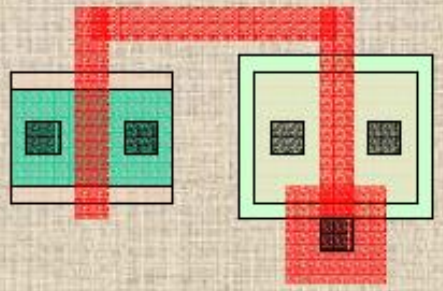
Implante P+





Contactos





Metal